

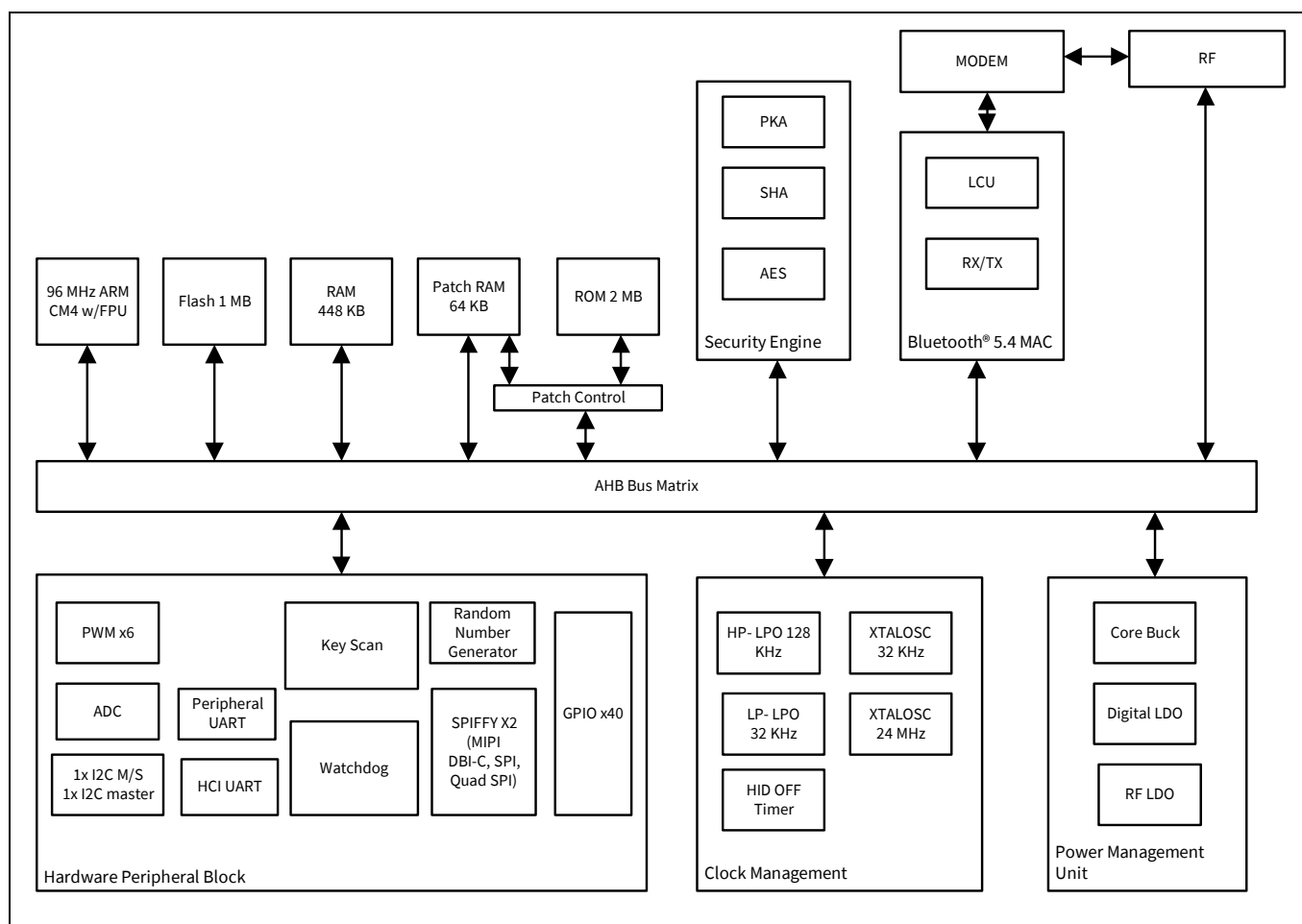
AIROC™ Bluetooth® & Bluetooth® LE system on chip

Enhanced low power

CYW20719 is a Bluetooth® 5.4-compliant, stand-alone baseband processor with an integrated 2.4 GHz transceiver with Bluetooth® LE, EDR and BR. The device is intended for use in audio, IoT, sensors (medical, home, security, and so forth) and human interface device (HID) applications. Manufactured using an advanced 40nm CMOS low-power fabrication process, CYW20719 employs high level of integration to reduce external components, thereby minimizing application footprint and costs.

This datasheet provides details of the functional, operational, and electrical characteristics of CYW20719 device. It is intended for hardware, design, application, and OEM engineers.

Functional block diagram



Features

- Bluetooth® subsystem
 - Complies with Bluetooth® core specification v5.4 with LE 2 Mbps
 - Supports basic rate (BR), enhanced data rate (EDR) 2&3 Mbps, Bluetooth® Low Energy
 - Supports adaptive frequency hopping (AFH)
 - TX power 5 dBm
 - RX sensitivity -95.5 dBm (Bluetooth® LE)
- Ultra-low-power radio
 - RX current 5.9 mA (Bluetooth® LE)
 - TX current 5.6 mA at 0 dBm (Bluetooth® LE)
- Coexistence support
 - Support for global coexistence Interface for easy coexistence implementation with select AIROC™ Infineon Wi-Fi devices
- MCU subsystem
 - 96-MHz Arm® Cortex®-M4 microcontroller unit MCU with floating point unit (FPU)
 - Supports serial wire debug (SWD)
 - Runs Bluetooth® stack and application
 - Option to execute from on-chip flash or RAM
- Memory subsystem
 - 1 MB flash
 - 512 KB RAM
 - 2 MB ROM that stores Bluetooth® stack and driver and offloads flash for user applications
- Audio features and interfaces
 - 1x I²S with master and slave modes
 - 1x PCM
 - PDM [2]
 - Analog front end for analog microphone [1]
- Clocks
 - On-chip 32 kHz oscillator (LP-LPO)
 - On-chip 128 kHz oscillator (HP-LPO)
 - 32 kHz crystal oscillator (Optional if low power modes not required)
 - 24 MHz crystal oscillator
 - 48-bit real time clock (RTC)
- Peripherals and communication
 - 6x 16-bit PWMs
 - Programmable key-scan matrix interface, up to 8x20 key-scanning matrix [1, 2]
 - Watchdog timer (WDT)
 - 1x peripheral UART, 1x UART for programming and HCI
 - 2x SPI (master or slave mode) Blocks (SPI, Quad SPI, and MIPI DBI-C)
 - 1x I²C master
 - 1x 28-channel ADC (10-ENoB for DC measurement and 12-ENoB for audio measurement)
 - Hardware security engine

Notes

1. Available only in WLCSP package.
2. Subjected to driver support in Bluetooth SDK.

Features

- General purpose input output (GPIO)
 - 16 GPIOs on QFN package
 - 40 GPIOs on WLCSP package
 - Support up to 3.63 V operation
 - Four GPIOs support 16 mA and 8 mA sink at 3.3 V and 1.8 V respectively
- Operating voltage and low-power support
 - Wide operating voltage range: 1.76 V to 3.63 V
 - 5 power modes to implement ultra-low power application – managed by real time operating system
 - 0.4 μ A current in HID-OFF^[2] mode (wake from GPIO).
- Packages
 - 5 mm \times 5 mm 40-pin quad flat no-lead (QFN)
 - 3.2 mm \times 3.1 mm 134-ball wafer level chip scale package (WLCSP)
- Software support
 - ModusToolbox™ software. Features are subject to support in the Bluetooth® SDK.
 - Check the latest version of the Bluetooth® SDK Technical brief for supported features.
- Applications
 - Wearables and fitness bands
 - Home automation
 - Blood pressure monitors and other medical applications
 - Proximity sensors
 - Key Fobs
 - Thermostats and thermometers
 - Toys

Table of contents

| | |
|--|-----------|
| Functional block diagram | 1 |
| Features | 2 |
| Table of contents | 4 |
| 1 Bluetooth® Baseband Core | 6 |
| 1.1 BQB and regulatory testing support | 6 |
| 2 MCU | 7 |
| 3 External reset | 8 |
| 4 Power Management Unit (PMU) | 9 |
| 5 Integrated radio transceiver | 10 |
| 5.1 Transmitter path | 10 |
| 5.1.1 Digital modulator | 10 |
| 5.1.2 Power amplifier | 10 |
| 5.2 Receiver path | 10 |
| 5.2.1 Digital demodulator and bit synchronizer..... | 10 |
| 5.2.2 Receiver signal strength indicator | 10 |
| 5.3 Local oscillator (LO) | 10 |
| 6 Peripheral and communication interfaces | 11 |
| 6.1 I2C compatible master | 11 |
| 6.2 HCI UART interface..... | 11 |
| 6.3 Peripheral UART interface | 11 |
| 6.4 Crystal oscillators..... | 11 |
| 6.4.1 24-MHz crystal oscillator | 11 |
| 6.4.2 32 kHz crystal oscillator | 12 |
| 6.5 Low-frequency clock sources..... | 13 |
| 6.6 GPIO ports | 14 |
| 6.7 Keyboard scanner (available only on WLCSP package)..... | 14 |
| 6.8 ADC | 14 |
| 6.9 PWM | 15 |
| 6.10 Serial peripheral interface block..... | 16 |
| 6.10.1 MIPI interface | 16 |
| 6.11 Pulse Density Modulation (PDM) microphone..... | 16 |
| 6.12 I2S interface | 16 |
| 6.13 PCM interface | 17 |
| 6.13.1 Slot mapping..... | 17 |
| 6.13.2 Frame synchronization | 17 |
| 6.13.3 Data formatting..... | 17 |
| 6.13.4 Burst PCM mode..... | 17 |
| 6.14 Security engine | 18 |
| 6.14.1 Random number generator..... | 18 |
| 6.15 Power modes..... | 18 |
| 7 Firmware | 19 |
| 8 Pin assignments and GPIOs | 20 |
| 8.1 40-pin QFN and WLCSP pin assignments..... | 20 |
| 8.2 40-pin QFN and WLCSP GPIOs..... | 23 |
| 9 Pin/ball maps | 32 |
| 9.1 40-pin QFN pin map | 32 |
| 9.2 WLCSP ball map | 33 |
| 10 Specifications | 38 |
| 10.1 Electrical characteristics | 38 |
| 10.1.1 Core buck regulator | 39 |
| 10.1.2 Recommended external component for core buck regulator..... | 39 |

Table of contents

| | |
|---|-----------|
| 10.1.3 Recommended external components for RFLDO..... | 39 |
| 10.1.4 Digital I/O characteristics | 40 |
| 10.1.5 ADC electrical characteristics..... | 40 |
| 10.1.6 Current consumption | 42 |
| 10.2 RF specifications | 42 |
| 10.3 Timing and AC characteristics..... | 47 |
| 10.3.1 UART timing | 47 |
| 10.3.2 SPI timing | 48 |
| 10.3.3 I2C compatible interface timing..... | 50 |
| 11 Mechanical information | 53 |
| 11.1 40-pin QFN package..... | 53 |
| 11.2 WLCSP package..... | 54 |
| 11.3 WLCSP package keep-out..... | 55 |
| 11.4 Tape reel and packaging specifications | 55 |
| 12 Ordering information | 56 |
| 13 Acronyms | 57 |
| 14 Document conventions..... | 59 |
| 14.1 Units of measure | 59 |
| Revision history | 60 |

1 Bluetooth® baseband core

The Bluetooth® baseband core (BBC) implements all time-critical functions required for high-performance Bluetooth® operation. The BBC manages the buffering, segmentation, and routing of data for all connections. It prioritizes and schedules all RX/TX activities including adv, paging, scanning, and servicing of connections. In addition to these functions, it independently handles the host controller interface (HCI) including all commands, events, and data flowing over HCI. The core also handles symbol timing, forward error correction (FEC), header error control (HEC), cyclic redundancy check (CRC), authentication, data encryption/decryption, and data whitening/dewhitening.

Table 1 Bluetooth® features

| Bluetooth® 1.0 | Bluetooth® 1.2 | Bluetooth® 2.0 |
|----------------------------|------------------------------|-----------------------------|
| Basic rate | Interlaced scans | EDR 2 Mbps and 3 Mbps |
| SCO | Adaptive frequency hopping | – |
| Paging and inquiry | eSCO | – |
| Page and inquiry scan | – | – |
| Sniff | – | – |
| Bluetooth® 2.1 | Bluetooth® 3.0 | Bluetooth® 4.0 |
| Secure simple pairing | Unicast connectionless data | Bluetooth® Low Energy |
| Enhanced inquiry response | Enhanced power control | – |
| Sniff subrating | eSCO | – |
| Bluetooth® 4.1 | Bluetooth® 4.2 | Bluetooth® 5.0 |
| Low duty cycle advertising | Data packet length extension | LE 2 Mbps |
| Dual mode | LE secure connection | Slot availability mask |
| LE link layer topology | Link layer privacy | High duty cycle advertising |

1.1 BQB and regulatory testing support

The CYW20719 fully supports Bluetooth® Test mode as described in Part 1:1 of the Specification of the Bluetooth® system v3.0. This includes the transmitter tests, normal and delayed loop back tests, and reduced hopping sequence.

In addition to the standard Bluetooth® Test mode, the CYW20719 also supports enhanced testing features to simplify RF debugging and qualification and type-approval testing. These features include:

- Fixed frequency carrier wave (unmodulated) transmission
 - Simplifies some type-approval measurements (Japan)
 - Aids in transmitter performance analysis
- Fixed frequency constant receiver mode
 - Receiver output directed to I/O pin
 - Allows for direct BER measurements using standard RF test equipment
 - Facilitates spurious emissions testing for receive mode
- Fixed frequency constant transmission
 - 8-bit fixed pattern or PRBS-9
 - Enables modulated signal measurements with standard RF test equipment

2 MCU

The CYW20719 includes a Cortex® M4 processor with 2 MB of ROM, 448 KB of data RAM, 64 KB of patch RAM, and 1 MB of on-chip flash. The CM4 has a maximum speed of 96 MHz. CYW20719 supports execution from on-chip flash (OCF).

The CM4 also includes a single precision IEEE 754 compliant floating point unit (FPU).

The CM4 runs all the Bluetooth® layers as well as application code. The ROM includes LM, HCI, L2CAP, GATT, as well as other stack layers freeing up the flash for application usage. A standard SWD Interface provides debugging support.

3 External reset

An external active-low reset signal, RESET_N, can be used to put the CYW20719 in the reset state. The RESET_N should be released only after the VDDO supply voltage level has been stabilized for at least 35 ms.

4 Power management unit (PMU)

Figure 1 shows the CYW20719 PMU block diagram. The CYW20719 includes an integrated buck regulator, a bypass LDO, a capless LDO for digital circuits and a separate LDO for RF. The bypass LDO automatically takes over from the buck once V_{bat} supply falls below 2.1 V.

The voltage levels shown in this figure are the default settings; the firmware may change voltage levels based on operating conditions.

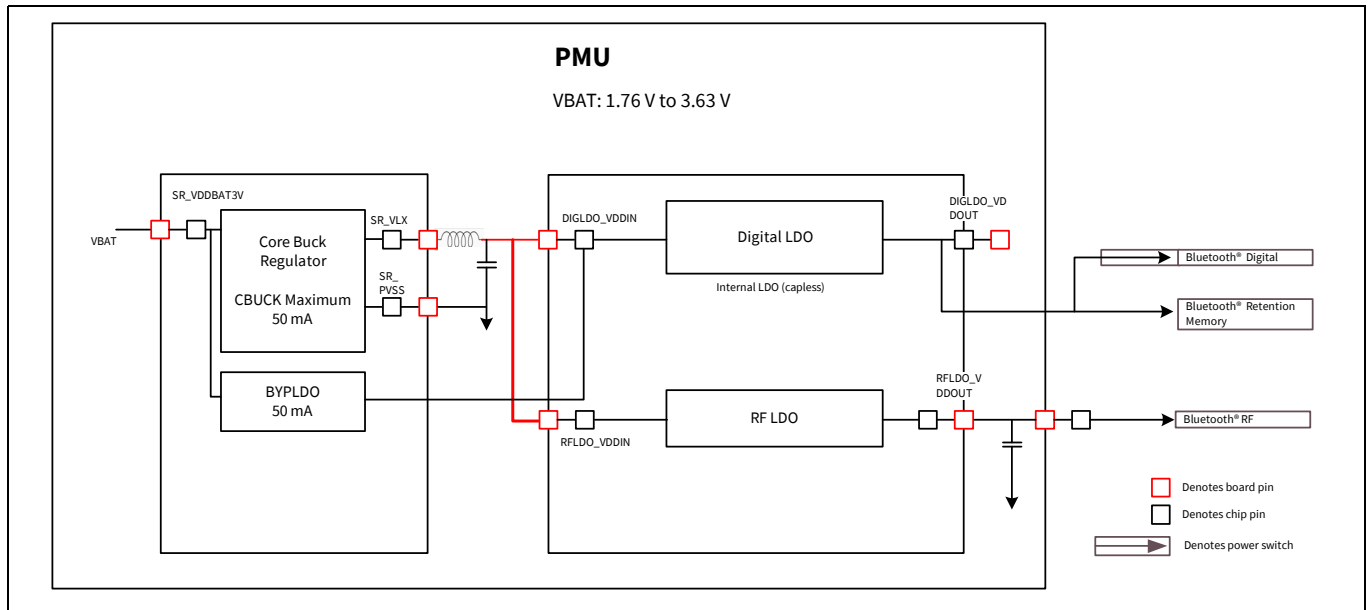


Figure 1 Default usage mode

5 Integrated radio transceiver

The CYW20719 has an integrated radio transceiver that has been designed to provide low power operation in the globally available 2.4 GHz unlicensed ISM band. It is fully compliant with the Bluetooth® radio specification and exceeds the requirements to provide the highest communication link quality of service.

5.1 Transmitter path

The CYW20719 features a fully integrated transmitter. The baseband transmit data is GFSK modulated in the 2.4 GHz ISM band.

5.1.1 Digital modulator

The digital modulator performs the data modulation and filtering required for the GFSK signal. The fully digital modulator minimizes any frequency drift or anomalies in the modulation characteristics of the transmitted signal.

5.1.2 Power amplifier

The CYW20719 has an integrated power amplifier (PA) that can transmit up to +5 dBm.

5.2 Receiver path

The receiver path uses a low IF scheme to down-convert the received signal for demodulation in the digital demodulator and bit synchronizer. The receiver path provides a high degree of linearity, and an extended dynamic range to ensure reliable operation in the noisy 2.4 GHz ISM band. The front-end topology, which has built-in out-of-band attenuation, enables the CYW20719 to be used in most applications without off-chip filtering.

5.2.1 Digital demodulator and bit synchronizer

The digital demodulator and bit synchronizer take the low-IF received signal and perform an optimal frequency tracking and bit synchronization algorithm.

5.2.2 Receiver signal strength indicator

The radio portion of the CYW20719 provides a receiver signal strength indicator (RSSI) to the baseband. This enables the controller to take part in a Bluetooth® power-controlled link by providing a metric of its own receiver signal strength to determine whether the transmitter should increase or decrease its output power.

5.3 Local oscillator (LO)

LO provides fast frequency hopping (1600 hops/second) across the 79 maximum available channels for BR/EDR functionality. The CYW20719 uses an internal loop filter.

6 Peripheral and communication interfaces

6.1 I²C compatible master

The CYW20719 provides a 2-pin I²C compatible Master interface to communicate with I²C compatible peripherals. The I²C compatible master supports the following clock speeds:

- 100 kHz
- 400 kHz
- 800 kHz (Not a standard I²C-compatible speed)
- 1 MHz (Compatibility with high-speed I²C-compatible devices is not guaranteed)

SCL and SDA lines can be routed to any of the P0-P39 GPIOs allowing for flexible system configuration. When used as SCL/SDA the GPIOs go into open drain mode and require an external pull-up for proper operation. I²C block does not support multi master capability by either master/slave devices.

6.2 HCI UART interface

The CYW20719 includes a UART interface for factory programming as well as when operating as a Bluetooth® HCI device in a system with an external host. The UART physical interface is a standard, 4-wire interface (RX, TX, RTS, and CTS) with adjustable baud rates from 115200 bps to 1.5 Mbps. Typical rates are 115200, 921600, 1500000 bps although intermediate speeds are also available. Support for changing the baud rate during normal HCI UART operation is included through a vendor-specific command. The CYW20719 UART operates correctly with the host UART as long as the combined baud rate error of the two devices is within $\pm 5\%$. The UART interface has a 1040-byte receive FIFO and a 1040-byte transmit FIFO to support enhanced data rates. The interface supports the Bluetooth® UART HCI (H4) specification. The default baud rate for H4 is 115.2 kbaud.

During HCI mode the DEV_WAKE signal can be programmed to wake up the CYW20719 or allow the CYW20719 to sleep when radio activities permit. The CYW20719 can also wake up the host as needed or allow the host to sleep via the HOST_WAKE signal. The combined two signals allow the host and the CYW20719 to optimize system power consumption by allowing independent control of low power modes. DEV_WAKE and HOST_WAKE signals can be enabled via a vendor specific command.

6.3 Peripheral UART interface

The CYW20719 has a second UART that may be used to interface to peripherals. This peripheral UART is accessed through the optional I/O ports, which can be configured individually and separately for each functional pin. The CYW20719 can map the peripheral UART to any GPIO (P0-P39). The Peripheral UART is functionally the same as HCI UART but with a 256 byte transmit and receive FIFO.

6.4 Crystal oscillators

6.4.1 24 MHz crystal oscillator

The CYW20719 uses a 24 MHz crystal oscillator (XTAL). The XTAL must have an accuracy of ± 20 ppm as defined by the Bluetooth® specification. Two external load capacitors are required to work with the crystal oscillator. The selection of the load capacitors is XTAL-dependent (see [Figure 2](#)).

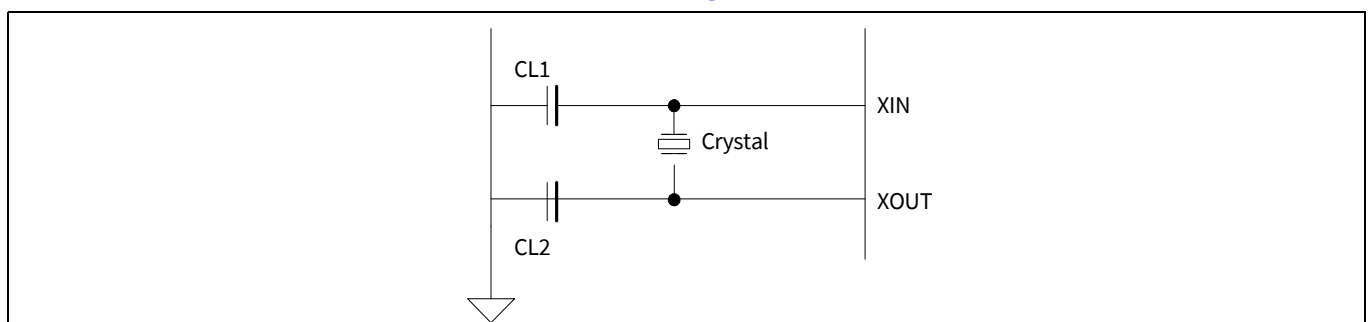


Figure 2 Recommended 24 MHz oscillator configuration

Table 2 Reference crystal electrical specifications

| Parameter | Conditions | Min. | Typ. | Max. | Unit |
|------------------------------|--|-------------|--------|------|------|
| Nominal frequency | – | – | 24.000 | – | MHz |
| Oscillation mode | – | Fundamental | | | – |
| Frequency accuracy | Includes operating temperature range and aging | – | – | ± 20 | ppm |
| Equivalent series resistance | – | – | – | 60 | Ω |
| Load capacitance | – | – | 8 | – | pF |
| Drive level | – | – | – | 200 | μW |
| Shunt capacitance | – | – | – | 2 | pF |

6.4.2 32 kHz crystal oscillator

The CYW20719 includes a 32 kHz oscillator to provide accurate timing during low power operations. **Figure 3** shows the 32 kHz XTAL oscillator with external components and **Table 3** lists the oscillator’s characteristics. This oscillator can be operated with 32.768 kHz crystal oscillator or be driven with a clock input at similar frequency. The default component values are: R1 = 10 MΩ and C1 = C2 = ~6 pF. The values of C1 and C2 are used to fine-tune the oscillator.

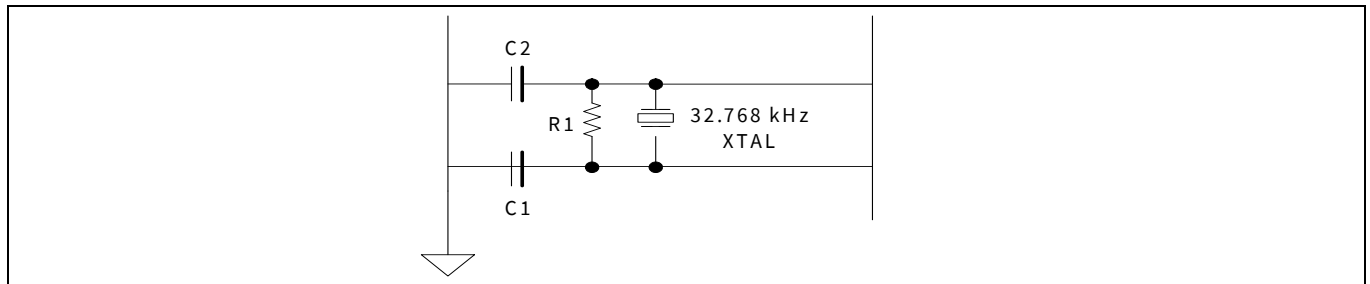


Figure 3 Recommended 32 kHz oscillator electrical specification

Table 3 Reference 32 kHz oscillator electrical specification

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-----------------------------|----------------------------|---|-----|--------|-----|------|
| Output frequency | F_{oscout} | – | – | 32.768 | – | kHz |
| Frequency tolerance | – | Crystal-dependent | – | 100 | – | ppm |
| Start-up time | T_{startup} | – | – | 500 | – | ms |
| XTAL drive level | P_{drv} | For crystal selection | – | – | 0.5 | μW |
| XTAL series resistance | R_{series} | For crystal selection | – | – | 70 | kΩ |
| XTAL shunt capacitance | C_{shunt} | For crystal selection | – | – | 2.2 | pF |
| External AC input amplitude | $V_{\text{IN}}(\text{AC})$ | $C_{\text{couple}} = 100 \text{ pF};$ $R_{\text{bias}} = 10 \text{ M}\Omega$ | 400 | – | – | mVpp |

6.5 Low-frequency clock sources

The 32 kHz low-frequency clock (lhl_lpo_32 kHz on the following figure) can be obtained from multiple sources. There are two internal low-power oscillators (LPOs) called the LP-LPO and HP-LPO and external crystal (OSC32K). The firmware determines the clock source to use among the available LPOs depending on the accuracy and power requirements. The preferred source is the external LPO (OSC32K) because it has good accuracy with the lowest current consumption. Internal LP-LPO has low current consumption and low accuracy whereas HP-LPO has higher accuracy and higher current consumption. The firmware assumes the external LPO has less than 250 PPM error with little or no jitter.

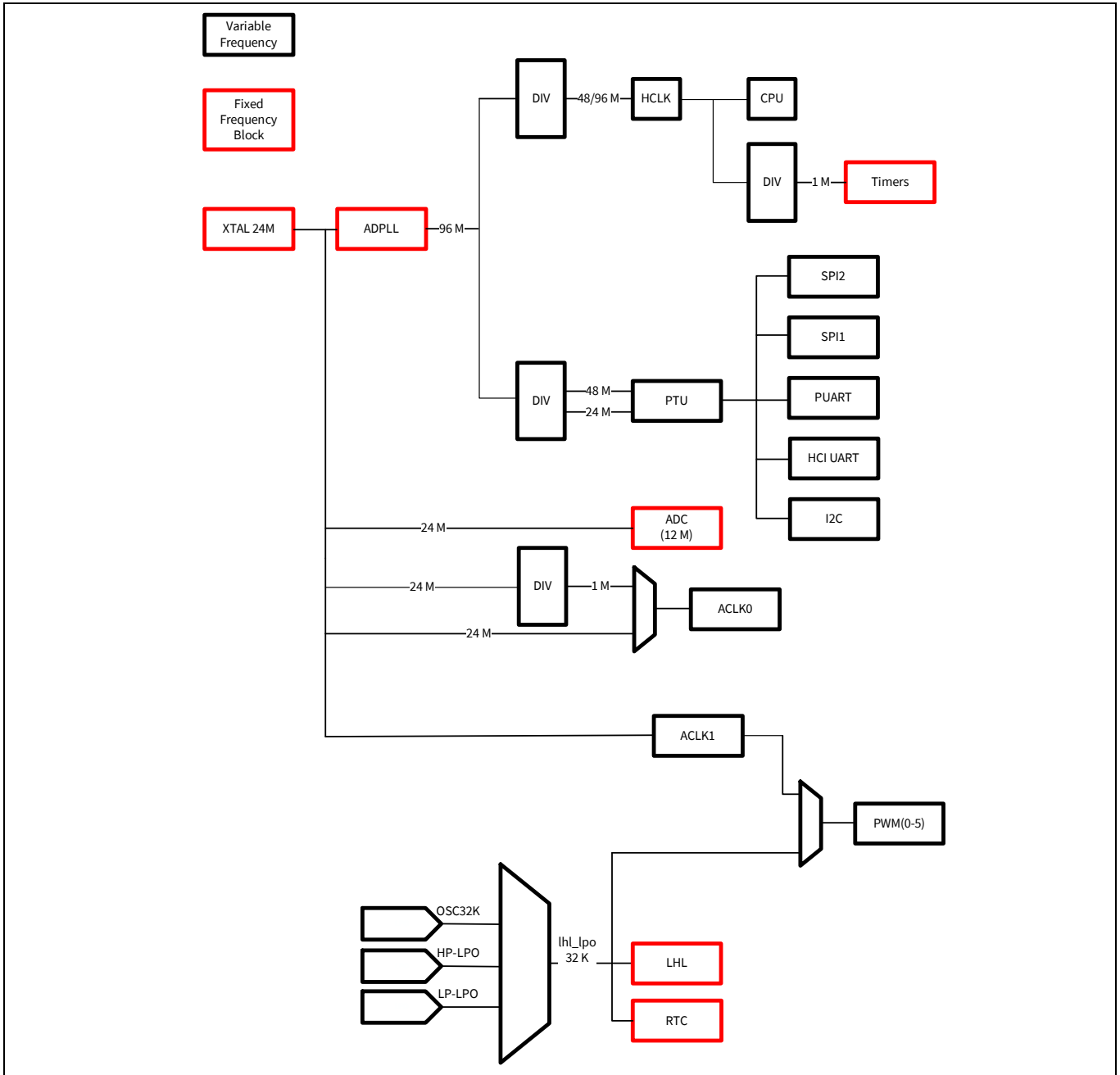


Figure 4 Simplified clock source

6.6 GPIO ports

The CYW20719 has 40 GPIOs labeled P0-P39 on WLCSP package and 16 GPIOs on QFN package. All GPIOs support the following:

- Programmable pull-up/down of approx 45 kΩ.
- Input disable, allowing pins to be left floating or analog signals connected without risk of leakage.
- Source/sink 8 mA at 3.3 V and 4 mA at 1.8 V.
- P15 is Bonded to the same pin as XTALI_32K on the QFN package (Pin 32). If External 32.768 kHz crystal is not used, then this pin can be used as GPIO P15. 0
- P26/P27/P28/P29 (some of these pins are not available on QFN package) sink/source 16 mA at 3.3 V and 8 mA at 1.8 V.
- Most peripheral functions can be assigned to any GPIO. For details, see [Table 4](#) and [Table 5](#).

6.7 Keyboard scanner (available only on WLCSP package)

CYW20719 includes a HW keyscanner that supports a maximum matrix size of 20 × 8. The scanner has 8 inputs (also referred to as rows) and 20 outputs (also referred to as columns). Keys are detected by driving the columns down sequentially and sampling the rows. The HW scanner includes support for ghost key detection and debouncing. The scanner can also operate in sleep and PDS mode allowing low power operation while continuing to detect/store all key strokes, up or down. In other low power modes, the scanner can continue to monitor the matrix and initiate exit to active mode upon detecting a change of state.

Note Subject to the driver support in Bluetooth® SDK.

6.8 ADC

CYW20719 includes a Σ - Δ ADC designed for audio (13 bits) and DC (10 bits) measurements. The ADC can measure the voltage on 28 GPIO. When used for analog inputs, the GPIOs must be placed in digital input disable mode to disconnect the digital circuit from the pin and avoid leakage. The internal band gap reference has $\pm 5\%$ accuracy without calibration. Calibration and digital correction schemes can be applied to reduce ADC absolute error and improve measurement accuracy in DC mode.

- P0, P1, P8-P18, P21-23, P28-P38 can be used as ADC inputs.

6.9 PWM

CYW20719 has six internal PWMs, labeled PWM0-5

- Each of the six PWM channels contains the following registers:
 - 16-bit initial value register (read/write)
 - 16-bit toggle register (read/write)
 - 16-bit PWM counter value register (read)
- PWM configuration register is shared among PWM0–5 (read/write). This 6-bit register is used:
 - To enable/disable each PWM channel
 - To select the clock of each PWM channel
 - To invert the output phase of each PWM channel

The application can access the PWM module through the FW driver.

Figure 5 shows the structure of one PWM channel.

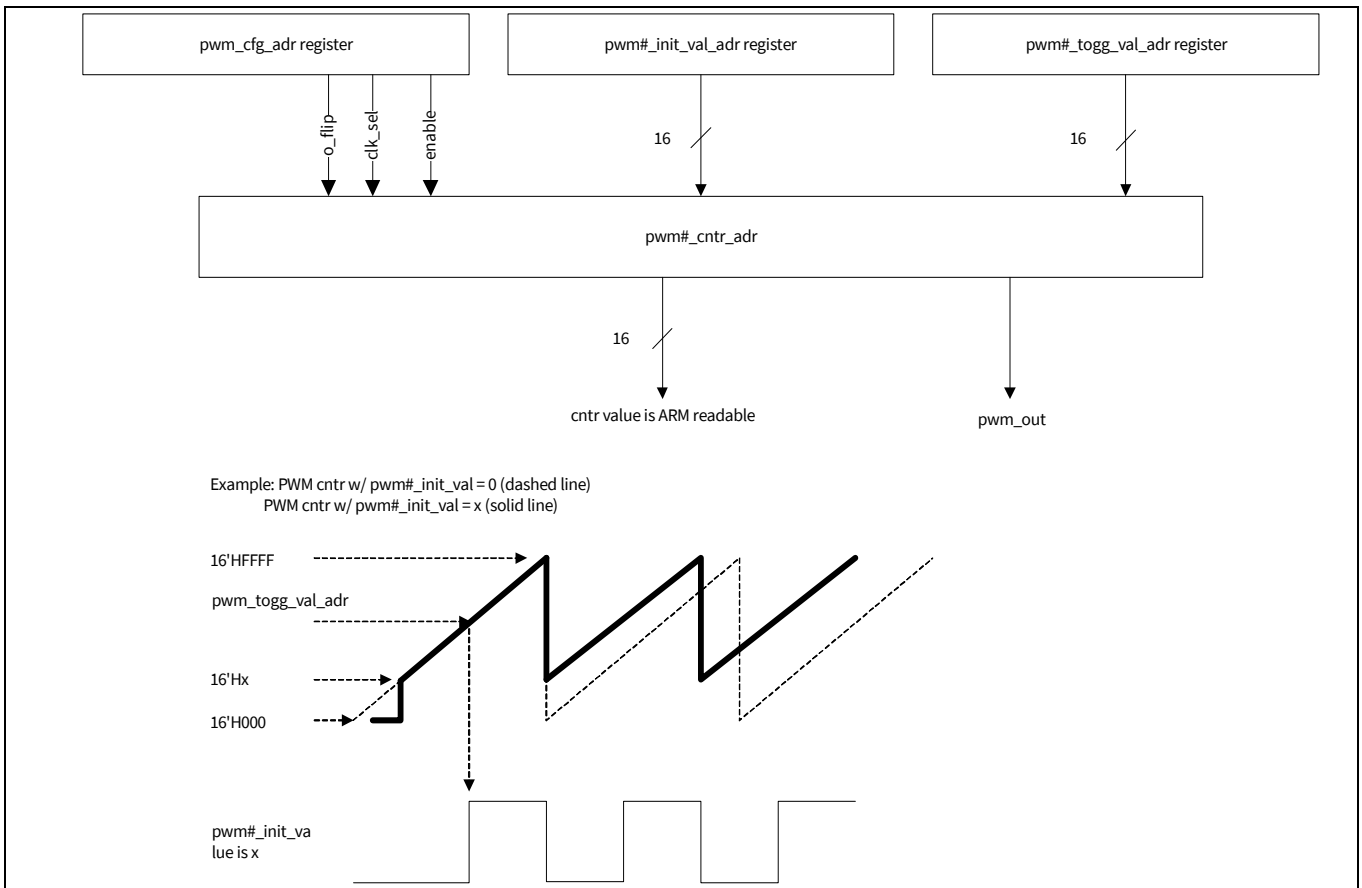


Figure 5 PWM block diagram

6.10 Serial peripheral interface block

CYW20719 has two independent SPI interfaces. Both interfaces support Single, Dual, and Quad mode SPI operations as well as MIPI DBI-C Interface. Either of the interface can be a master/slave. SPI2 can support only one slave. SPI1 has a 1024 byte transmit and receive buffers which is shared with the host UART interface. SPI2 has a dedicated 256 byte transmit and receive buffers. To support more flexibility for user applications, CYW20719 has optional I/O ports that can be configured individually and separately for each functional pin. SPI I/O voltage depends on VDDO.

6.10.1 MIPI interface

There are three options in DBI type-C corresponding to 9-bit, 16-bit, and 8-bit modes. The CYW20719 plays the role of host, and only the 9-bit and 8-bit modes (option 1 and option 3 in DBI-C spec) are supported. In the 9-bit mode, the SCL, CS, MOSI, and MISO pins are used. In the 8-bit mode, an additional pin DCX, indicating whether the current outgoing bit stream is a command or data byte is required.

6.11 Pulse Density Modulation (PDM) microphone

CYW20719 accepts a $\Sigma\Delta$ -based one-bit PDM input stream and outputs filtered samples at either 8 kHz or 16 kHz sampling rates. The PDM signal derives from an external kit that can process analog microphone signals and generate digital signals. The PDM input shares the filter path with the aux ADC. Two types of data rates can be supported:

- 8 kHz
- 16 kHz

The external digital microphone takes in a 2.4 MHz clock generated by the CYW20719 and outputs a PDM signal which is registered by the PDM interface with either the rising or falling edge of the 2.4 MHz clock selectable through a programmable control bit. The design can accommodate two simultaneous PDM input channels, so stereo voice is possible.

Note Subject to the driver support in Bluetooth® SDK.

6.12 I²S interface

The CYW20719 supports a single I²S digital audio port in both master and slave modes. The I²S signals are:

- I²S clock: I²S SCK
- I²S word select: I²S WS
- I²S data out: I²S DO
- I²S data in: I²S DI

I²S SCK and I²S WS become outputs in master mode and inputs in slave mode, while I²S DO always stays as an output and I²S DI stays as input. The channel word length is fixed to 16 bits (frame length of 32 bits) and the data is justified so that the MSB of the left-channel data is aligned with the MSB of the I²S bus, as per I²S Specifications. The MSB of each data word is transmitted one bit clock cycle after the I²S WS transition, synchronous with the falling edge of bit clock. Left Channel data is transmitted when I²S WS is low, and right-channel data is transmitted when I²S WS is high. Data bits sent by the CYW20719 are synchronized with the falling edge of I²S SCK and should be sampled by the receiver on the rising edge of the I²S SCK.

The I²S port is primarily used to transfer audio samples while using the A2DP profile^[3]. The A2DP controller is half duplex and the direction of the audio samples depend on the A2DP role (sink/source). The I²S clock in the master mode can either be:

- 44.1 kHz × 32 bits per frame = 1411.2 kHz
- 48 kHz × 32 bits per frame = 1536 kHz

In the slave mode, any clock rate is supported up to a maximum of 3.072 MHz.

Note

3. The I²S port cannot be used at the application level for purposes other than routing A2DP audio samples.

Note PCM interface shares HW with the I²S interface which means that both voice and audio cannot be routed at the same time.

6.13 PCM interface

CYW20719 includes a PCM interface that can connect to linear PCM codec devices in master or slave mode. In master mode, the CYW20719 generates the PCM_CLK and PCM_SYNC signals. In slave mode, these signals are provided by another device on the PCM interface and are inputs to the CYW20719. Some of the parameters of the PCM interface may be configured by the host.

The PCM interface is used for full-duplex bi-directional transfer of 8K or 16K voice samples from and to a SCO or eSCO connection^[4]. By default, the PCM interface runs in an I²S compatible mode, which allows the CYW20719 to transfer voice samples to I²S devices.

Note PCM interface shares HW with the I²S interface which means that both voice and audio cannot be routed simultaneously.

6.13.1 Slot mapping

CYW20719 supports up to three simultaneous full-duplex SCO or eSCO channels through the PCM Interface, when operating in HCI mode. These three channels are time-multiplexed onto the single PCM interface by using a time-slotting scheme where the 8 kHz or 16 kHz voice sample interval is divided into as many as 16 slots. The number of slots is dependent on the selected interface rate (128 kHz, 256kHz, 512 kHz, 1024 kHz or 2048 kHz). The corresponding number of slots for these interface rate is 1, 2, 4, 8, and 16, respectively. Transmit and receive PCM data from an SCO channel is always mapped to the same slot. The PCM data output driver tristates its output on unused slots to allow other devices to share the same PCM interface signals. The data output driver tristates its output after the falling edge of the PCM clock during the last bit of the slot.

6.13.2 Frame synchronization

CYW20719 supports both short and long-frame synchronization in both master and slave modes and can be configured from the host. In short frame synchronization mode, the frame synchronization signal is an active-high pulse at the audio frame rate that is a single-bit period in width and is synchronized to the rising edge of the bit clock. The PCM slave looks for a high on the falling edge of the bit clock and expects the first bit of the first slot to start at the next rising edge of the clock. In long-frame synchronization mode, the frame synchronization signal is again an active-high pulse at the audio frame rate; however, the duration is three bit periods and the pulse starts coincident with the first bit of the first slot.

6.13.3 Data formatting

CYW20719 may be configured to generate or accept several different data formats. For conventional narrow band speech mode, the CYW20719 always uses 13 of the 16 bits in each PCM frame. The location and order of these 13 bits can be configured to support various data formats on the PCM interface. The remaining three bits are ignored on the input and may be filled with 0s, 1s, a sign bit, or a programmed value on the output. The default format is 13-bit 2's complement data, left justified, filled with 0's and clocked MSB first.

6.13.4 Burst PCM mode

In this mode of operation, the PCM bus runs at a significantly higher rate of operation to allow the host to duty cycle its operation and save current. In this mode of operation, the PCM bus can operate at a rate of up to 24 MHz. This mode of operation is initiated with an HCI command from the host.

Note

4. The PCM interface cannot be used as a generic serial interface at the application level. It can only be used for routing SCO or eSCO voice samples.

6.14 Security engine

CYW20719 includes a hardware security accelerator which greatly decreases the time required to perform typical security operations. This security engine includes:

- Public key acceleration (PKA) cryptography
- AES-CTR/CBC-MAC/CCM acceleration
- SHA2 message hash and HMAC acceleration
- RSA encryption and decryption of modulus sizes up to 2048 bits
- Elliptic curve Diffie-Hellman in prime field GF(p)

Note Security engine is used only by Bluetooth® stack to reduce CPU overhead. It is not available for application use

6.14.1 Random number generator

This hardware block is used for key generation for Bluetooth®.

Note Availability for use by the application is subject to the support in Bluetooth® SDK.

6.15 Power modes

CYW20719 supports the following HW power modes:

- Active mode - Normal operating mode in which all peripherals are available and the CPU is active.
- Idle mode- In this mode, the CPU is in “Wait for Interrupt” (WFI) and the HCLK, which is the high frequency clock derived from the main crystal oscillator is running at a lower clock speed. Other clocks are active and the state of the entire chip is retained.
- Sleep mode - In this mode, CPU is in WFI and the HCLK is not running. The PMU determines if the other clocks can be turned off and does accordingly. State of the entire chip is retained, the internal LDOs run at a lower voltage (voltage is managed by the PMU), and SRAM is retained.
- Power Down Sleep (PDS) mode -This mode is an extension of the PMU Sleep wherein most of the peripherals such as UART and SPI are turned off. The entire memory is retained, and on wakeup the execution resumes from where it paused.
- Shut Down Sleep (SDS) mode -Everything is turned off except I/O Power Domain, RTC, and LPO. The device can come out of this mode either due to Bluetooth® activity or by an external interrupt. Before going into this mode, the application can store some bytes of data into “Always On RAM” (AON). When the device comes out of this mode, the data from AON is restored. After waking from SDS, the application will start from the beginning (warmboot) and has to restore its state based on information stored in AON. In the SDS mode, a single Bluetooth® task with no data activity, such as an ACL connection, Bluetooth® LE connection, or Bluetooth® LE advertisement can be performed.
- HID-OFF^[5] (Timed-Wake) mode -The device can enter this mode asynchronously, that is, the application can force the device into this mode at any time. I/O Power Domain, RTC, and LPO are the only active blocks. A timer that runs off the LPO is used to wake the device up after a predetermined fixed time.
- HID-OFF^[5] (External Interrupt-Waked) mode - This mode is similar to Timed-Wake, but in HID-OFF mode even the LPO and RTC are turned off. Therefore, the only wakeup source is an external interrupt.

Transition between power modes is handled by the on-chip firmware with host/application involvement. See [Firmware](#) Section for details.

Note

5. Subject to driver support in Bluetooth® SDK.

7 Firmware

CYW20719 ROM firmware runs on a real time operating system and handles the programming and configuration of all on-chip hardware functions as well as the Bluetooth® LE baseband, Link Manager (LM), HCI, Generic Attribute Profile (GATT), Attribute Protocol (ATT), Logical Link Control and Adaptation Protocol (L2CAP) and Service Discovery Protocol (SDP) layers. The ROM also includes drivers for on-chip peripherals as well as handling on-chip power management functions including transitions between different power modes.

CYW20719 is fully supported by the ModusToolbox™ software platform. Bluetooth® SDK releases provide latest ROM patches, drivers, and sample applications allowing customized applications using CYW20719 to be built quickly and efficiently.

Refer to CYW20719 Product Guide for details on the firmware architecture, driver documentation, power modes and how to write applications/profiles using CYW20719.

8 Pin assignments and GPIOs

This section addresses both QFN and WLCSP pin assignments and GPIOs for CYW20719 device.

8.1 40-pin QFN and WLCSP pin assignments

Table 4 40-pin QFN and WLCSP pin assignments

| Pin name | Pin number | | I/O | Power domain | Description |
|------------------------|------------|-------------------------------|-----|--------------|---|
| | QFN-40 | WLCSP | | | |
| Microphone | | | | | |
| ADC_avddBAT | – | 5 | I | VDDIO | VDDIO |
| ADC_AVDDC | – | 3 | I | – | No connect |
| Mic_avdd | – | 19 | I | MIC_AVDD | Microphone supply |
| Micbias | – | 32 | I | MIC_AVDD | Microphone bias supply |
| Micn | – | 4 | I | MIC_AVDD | Microphone negative input |
| Micp | – | 18 | I | MIC_AVDD | Microphone positive input |
| ADC_AVSS | – | 34 | I | AVSS | Analog ground |
| ADC_AVSSC | – | 17 | I | AVSS | Analog ground |
| ADC_REFGND | – | 33 | I | AVSS | Analog reference ground |
| Mic_avss | – | 47 | I | AVSS | Microphone analog ground |
| Baseband supply | | | | | |
| BT_VDDO | 25 | 1,8,9,11,14,26,29,42,56,66,91 | I | VDDO | I/O pad power supply |
| BT_VDDC | – | 2,43,58,74,99 | I/O | VDDC | Baseband core power supply |
| VDDO | 39 | – | I | VDDO | LHL PAD power supply. Can be tied to BT_VDDO. |
| RF power supply | | | | | |
| BT_PAVDD | 17 | 116 | I | PAVDD | PA supply |
| BT_PLLVDD1p2 | 21 | 106 | I | PLLVDD1P2 | RFPLL and crystal oscillator supply |
| BT_VCOVDD1p2 | 20 | 125 | I | VCOVDD1P2 | VCO supply |
| BT_IFVDD1P2 | 19 | 110 | I | IFVDD1P2 | IFPLL power supply |
| Onboard LDO's | | | | | |
| DIGLDO_VDDIN | 16 | 127 | I | – | Internal digital LDO input |
| DIGLDO_VDDOUT | – | 126 | O | – | Internal digital LDO output |
| RFLDO_VDDIN | 15 | 111 | I | – | RF LDO input |
| RFLDO_VDDOUT | 14 | 128 | O | – | RF LDO output |
| SR_VDDBAT3V | 13 | 129 | I | – | Core buck input |
| VDDBAT3V | – | 120 | I | – | Core buck input |
| SR_VLX | 12 | 121 | O | – | Core buck output |
| Ground pins | | | | | |
| BT_PAVSS | – | 123 | I | VSS | Ground |
| BT_PLLVSS | – | 107 | I | VSS | Ground |

Table 4 40-pin QFN and WLCSP pin assignments (continued)

| Pin name | Pin number | | I/O | Power domain | Description |
|----------------|------------|---|-------|--------------|---|
| | QFN-40 | WLCSP | | | |
| BT_VCOVSS | – | 119 | I | VSS | Ground |
| BT_IFVSS | – | 115 | I | VSS | Ground |
| BT_VSSC | – | 30, 57, 75, 87, 117, 118, 124, 133, 134 | I | VSS | Ground |
| VSSC | – | 112 | I | VSS | Ground |
| VSSO_0 | – | 10,1325, 28,72, 96,101 | I | VSS | Ground |
| SR_PVSS | – | 130 | I | VSS | Ground |
| xtal_avss | – | 35 | I | XTAL_AVSS | Crystal ground |
| PMU_AVSS | – | 113,114 | I | PMU_AVSS | PMU ground |
| VSS | H | – | I | VSS | Exposed center pad, connect to ground. |
| UART | | | | | |
| BT_UART_CTS_N | 30 | 15 | I, PU | VDDO | Clear to send (CTS) for HCI UART interface. Leave unconnected if not used. |
| BT_UART_RTS_N | 29 | 31 | O, PU | VDDO | Request to send (RTS) for HCI UART interface. Leave unconnected if not used. |
| BT_UART_RXD | 27 | 45 | I | VDDO | UART serial input. Serial data input for the HCI UART interface. |
| BT_UART_TXD | 28 | 46 | O, PU | VDDO | UART serial output. Serial data output for the HCI UART interface. |
| Crystal | | | | | |
| BT_XTALI | 22 | 105 | I | PLLVD1P2 | Crystal oscillator input. See “The XTAL must have an accuracy of ± 20 ppm as defined by the Bluetooth® specification. Two external load capacitors are required to work with the crystal oscillator. The selection of the load capacitors is XTAL-dependent (see Figure 2)” for options. |
| BT_XTALO | 23 | 104 | O | PLLVD1P2 | Crystal oscillator output. |
| XTALI_32K | 32 | 6 | I | VDDO | Low-power oscillator input. |
| XTALO_32K | 31 | 20 | O | VDDO | Low-power oscillator output. |
| BT_RF | 18 | 132 | – | – | RF Antenna Port |
| BT_CLK_REQ | – | 68 | O | N/A | Used for shared-clock application. |
| JTAG_SEL | 11 | 102 | – | – | Reserved Arm® JTAG debug mode control. Connect to GND for all applications. |

Pin assignments and GPIOs

Table 4 **40-pin QFN and WLCSP pin assignments** *(continued)*

| Pin name | Pin number | | I/O | Power domain | Description |
|--------------------------|------------|---------------------------------|-----|--------------|---|
| | QFN-40 | WLCSP | | | |
| RST_N | 10 | 103 | I | VDDO | Active-low system reset with internal pull-up resistor. |
| Reserved pins | | | | | |
| Reserved | 26 | 21, 36, 49, 61, 77, 84, 85, 108 | N/A | N/A | Reserved. Leave unconnected. |
| Reserved, Connect to GND | – | 16, 92 | N/A | N/A | Reserved, connect to GND |

8.2 40-pin QFN and WLCSP GPIOs

Table 5 40-pin QFN and WLCSP GPIOs

| Pin name | Pin number | | I/O | Power domain | Description |
|--------------|------------|-------|-----|--------------|--|
| | QFN-40 | WLCSP | | | |
| BT_DEV_WAKE | – | 86 | I | VDDO | A signal from the host to the CYW20719 indicating that the host requires attention. |
| BT_HOST_WAKE | 24 | 76 | O | VDDO | A signal from the CYW20719 device to the host indicating that the Bluetooth® device requires attention. |
| BT_GPIO_2 | – | 44 | I/O | VDDO | GPIO: Can also be configured as a GCI Pin |
| BT_GPIO_3 | – | 59 | I/O | VDDO | GPIO: Can also be configured as a GCI Pin |
| BT_GPIO_4 | – | 79 | I/O | VDDO | GPIO: Can also be configured as a GCI Pin |
| BT_GPIO_5 | – | 78 | I/O | VDDO | GPIO: Can also be configured as a GCI Pin |
| P0 | 3 | 93 | I/O | VDDO | <ul style="list-style-type: none"> • GPIO: P0 • Keyboard scan input (row): KSI0 • A/D converter input 29 • Supermux I/O functions as defined in Table 6. |
| P1 | 4 | 54 | I/O | VDDO | <ul style="list-style-type: none"> • GPIO: P1 • Keyboard scan input (row): KSI1 • A/D converter input 28 • Supermux I/O functions as defined in Table 6 |
| P2 | 34 | 60 | I/O | VDDO | <ul style="list-style-type: none"> • GPIO: P2 • Keyboard scan input (row): KSI2 • Supermux I/O functions as defined in Table 6 |
| P3 | – | 22 | I/O | VDDO | <ul style="list-style-type: none"> • GPIO: P3 • Keyboard scan input (row): KSI3 • Supermux I/O functions as defined in Table 6 |
| P4 | 35 | 23 | I/O | VDDO | <ul style="list-style-type: none"> • GPIO: P4 • Keyboard scan input (row): KSI4 • Supermux I/O functions as defined in Table 6 |

Notes

6. All GPIOs are super mux. All GPIOs can be programmed for any alternative functions as listed in [Table 6](#) and [Table 7](#).
7. During power-on reset, all inputs are disabled.
8. P15 and P37 should not be driven high externally while the part is held in reset (they can be floating or driven low). Failure to do so may cause some current to flow through these pins until the part comes out of reset.

Table 5 **40-pin QFN and WLCSP GPIOs** (continued)

| Pin name | Pin number | | I/O | Power domain | Description |
|----------|------------|-------|-----|--------------|--|
| | QFN-40 | WLCSP | | | |
| P5 | – | 37 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P5 Keyboard scan input (row): KSI5 Supermux I/O functions as defined in Table 6 |
| P6 | 36 | 50 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P6 Keyboard scan input (row): KSI6 Supermux I/O functions as defined in Table 6 |
| P7 | 37 | 62 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P7 Keyboard scan input (row): KSI7 Supermux I/O functions as defined in Table 6 |
| P8 | – | 69 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P8 A/D converter input 27 Supermux I/O functions as defined in Table 6 |
| P9 | – | 52 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P9 A/D converter input 26 External T/R switch control: tx_pd Supermux I/O functions as defined in Table 6 |
| P10 | 40 | 63 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P10 Keyboard scan output (column): KSO2 A/D converter input 25 Supermux I/O functions as defined in Table 6 |
| P11 | – | 70 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P11 A/D converter input 24 Supermux I/O functions as defined in Table 6 |
| P12 | – | 40 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P12 A/D converter input 23 Supermux I/O functions as defined in Table 6 |

Notes

- All GPIOs are super mux. All GPIOs can be programmed for any alternative functions as listed in [Table 6](#) and [Table 7](#).
- During power-on reset, all inputs are disabled.
- P15 and P37 should not be driven high externally while the part is held in reset (they can be floating or driven low). Failure to do so may cause some current to flow through these pins until the part comes out of reset.

Table 5 40-pin QFN and WLCSP GPIOs (continued)

| Pin name | Pin number | | I/O | Power domain | Description |
|----------|------------|-------|-----|--------------|---|
| | QFN-40 | WLCSP | | | |
| P13 | – | 71 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P13 A/D converter input 22 Supermux I/O functions as defined in Table 6 |
| P14 | – | 24 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P14 A/D converter input 21 Supermux I/O functions as defined in Table 6 |
| P15 | 32 | 7 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P15 A/D converter input 20 Supermux I/O functions as defined in Table 6 |
| P16 | 33 | 48 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P16 A/D converter input 19 Supermux I/O functions as defined in Table 6 |
| P17 | 38 | 38 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P17 A/D converter input 18 Supermux I/O functions as defined in Table 6 |
| P18 | – | 51 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P18 A/D converter input 17 Supermux I/O functions as defined in Table 6 |
| P19 | – | 39 | I/O | VDDO | Reserved for system use. Leave unconnected. |
| P20 | – | 12 | I/O | VDDO | Reserved for system use. Leave unconnected. |
| P21 | – | 53 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P21 A/D converter input 14 Supermux I/O functions as defined in Table 6 |

Notes

- All GPIOs are super mux. All GPIOs can be programmed for any alternative functions as listed in [Table 6](#) and [Table 7](#).
- During power-on reset, all inputs are disabled.
- P15 and P37 should not be driven high externally while the part is held in reset (they can be floating or driven low). Failure to do so may cause some current to flow through these pins until the part comes out of reset.

Table 5 40-pin QFN and WLCSP GPIOs (continued)

| Pin name | Pin number | | I/O | Power domain | Description |
|----------|------------|-------|-----|--------------|--|
| | QFN-40 | WLCSP | | | |
| P22 | – | 27 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P22 A/D converter input 13 Supermux I/O functions as defined in Table 6 |
| P23 | – | 64 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P23 A/D converter input 12 Supermux I/O functions as defined in Table 6 |
| P24 | – | 90 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P24 Supermux I/O functions as defined in Table 6 |
| P25 | 8 | 97 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P25 Supermux I/O functions as defined in Table 6 |
| P26 | 7 | 83 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P26 Current: 16 mA sink Supermux I/O functions as defined in Table 6 |
| P27 | – | 94 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P27 Current: 16 mA sink Supermux I/O functions as defined in Table 6 |
| P28 | 1 | 41 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P28 A/D converter input 11 Current: 16 mA sink Supermux I/O functions as defined in Table 6 |
| P29 | 2 | 80 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P29 A/D converter input 10 Current: 16 mA sink Supermux I/O functions as defined in Table 6 |

Notes

- All GPIOs are super mux. All GPIOs can be programmed for any alternative functions as listed in [Table 6](#) and [Table 7](#).
- During power-on reset, all inputs are disabled.
- P15 and P37 should not be driven high externally while the part is held in reset (they can be floating or driven low). Failure to do so may cause some current to flow through these pins until the part comes out of reset.

Table 5 40-pin QFN and WLCSP GPIOs (continued)

| Pin name | Pin number | | I/O | Power domain | Description |
|--------------------|------------|-------|-----|--------------|--|
| | QFN-40 | WLCSP | | | |
| P30 | – | 95 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P30 A/D converter input 9 Supermux I/O functions as defined in Table 6 |
| P31 | – | 73 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P31 A/D converter input 8 Supermux I/O functions as defined in Table 6 |
| P32 | – | 98 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P32 A/D converter input 7 Supermux I/O functions as defined in Table 6 |
| P33 | 9 | 100 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P33 A/D converter input 6 Supermux I/O functions as defined in Table 6 |
| P34 | 5 | 81 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P34 A/D converter input 5 Supermux I/O functions as defined in Table 6 |
| P35 | – | 65 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P35 A/D converter input 4 Supermux I/O functions as defined in Table 6 |
| P36 | – | 55 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P36 A/D converter input 3 Supermux I/O functions as defined in Table 6 |
| P37 ^[8] | – | 88 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P37 A/D converter input 2 Supermux I/O functions as defined in Table 6 |

Notes

- All GPIOs are super mux. All GPIOs can be programmed for any alternative functions as listed in [Table 6](#) and [Table 7](#).
- During power-on reset, all inputs are disabled.
- P15 and P37 should not be driven high externally while the part is held in reset (they can be floating or driven low). Failure to do so may cause some current to flow through these pins until the part comes out of reset.

Table 5 40-pin QFN and WLCSP GPIOs (continued)

| Pin name | Pin number | | I/O | Power domain | Description |
|----------|------------|-------|-----|--------------|--|
| | QFN-40 | WLCSP | | | |
| P38 | 6 | 89 | I/O | VDDO | <ul style="list-style-type: none"> GPIO: P38 A/D converter input 1 Supermux I/O functions as defined in Table 6 |
| P39 | – | 82 | I/O | VDDO | Reserved for system use. Leave unconnected. |

Strapping pins

| | | | | | |
|-------------|---|-----|---|------|--|
| BT_TM1 | – | 67 | I | – | Device test mode control. Connect to GND for all applications. |
| PMU_DISABLE | – | 109 | I | VDDO | PMU Enable/Disable. Connected to ground. |

Notes

- All GPIOs are super mux. All GPIOs can be programmed for any alternative functions as listed in [Table 6](#) and [Table 7](#).
- During power-on reset, all inputs are disabled.
- P15 and P37 should not be driven high externally while the part is held in reset (they can be floating or driven low). Failure to do so may cause some current to flow through these pins until the part comes out of reset.

Table 6 **GPIO supermux input functions**

| Input | Description |
|-----------------|------------------------------|
| SWDCK | Serial Wire Debugger Clock |
| SWDIO | Serial Wire Debugger I/O |
| spiffy1_clk[s] | SPIFFY 1 Clock (Slave) |
| spiffy1_cs[s] | SPIFFY 1 Chip Select (Slave) |
| spiffy1_mosi[s] | SPIFFY 1 MOSI (Slave) |
| spiffy1_miso[m] | SPIFFY 1 MISO (Master) |
| spiffy1_io2 | SPIFFY 1 I/O 2 (Quad SPI) |
| spiffy1_io3 | SPIFFY 1 I/O 3 (Quad SPI) |
| spiffy1_int[s] | SPIFFY 1 Interrupt (Slave) |
| spiffy2_clk[s] | SPIFFY 2 Clock (Slave) |
| spiffy2_cs[s] | SPIFFY 2 Chip Select (Slave) |
| spiffy2_mosi[s] | SPIFFY 2 MOSI (Slave) |
| spiffy2_miso[m] | SPIFFY 2 MISO (Master) |
| spiffy2_io2 | SPIFFY 2 I/O 2 |
| spiffy2_io3 | SPIFFY 2 I/O 3 |
| spiffy2_int[s] | SPIFFY 2 Interrupt (Slave) |
| puart_rx | Peripheral UART RX |
| puart_cts_n | Peripheral UART CTS |
| SCL | I2C Clock |
| SDA | I2C Data |
| PCM_IN | PCM Input |
| PCM_CLK | PCM Clock |
| PCM_SYNC | PCM Sync |
| I2S_DI | I2S Data Input |
| I2S_WS | I2S Word Select |
| I2S_CLK | I2S Clock |
| PDM_IN_Ch_1 | PDM Input Channel 1 |
| PDM_IN_Ch_2 | PDM Input Channel 2 |

Table 7 GPIO supermux output functions

| Output | Description |
|--|-----------------------------------|
| do_P# (data out of GPIO. For example: 0) | |
| kso0 | Key Scan output 0 |
| kso1 | Key Scan output 1 |
| kso2 | Key Scan output 2 |
| kso3 | Key Scan output 3 |
| kso4 | Key Scan output 4 |
| kso5 | Key Scan output 5 |
| kso6 | Key Scan output 6 |
| kso7 | Key Scan output 7 |
| kso8 | Key Scan output 8 |
| kso9 | Key Scan output 9 |
| kso10 | Key Scan output 10 |
| kso11 | Key Scan output 11 |
| kso12 | Key Scan output 12 |
| kso13 | Key Scan output 13 |
| kso14 | Key Scan output 14 |
| kso15 | Key Scan output 15 |
| kso16 | Key Scan output 16 |
| kso17 | Key Scan output 17 |
| kso18 | Key Scan output 18 |
| kso19 | Key Scan output 19 |
| do_P# ^ pwm0 | PWM Channel 0 |
| do_P# ^ pwm1 | PWM Channel 1 |
| do_P# ^ pwm2 | PWM Channel 2 |
| do_P# ^ pwm3 | PWM Channel 3 |
| do_P# ^ pwm4 | PWM Channel 4 |
| do_P# ^ pwm5 | PWM Channel 5 |
| aclk0 | Auxiliary clock Output 0 |
| aclk1 | Auxiliary clock Output 1 |
| HID_OFF | HID-OFF Indicator |
| pa_ramp | External PA ramp |
| tx_pu | External PA Control Signal |
| rx_pu | External PA Control Signal |
| SWDIO | Serial Wire Debugger Input/Output |
| puart_tx (uart2_tx) | Peripheral UART TX |
| puart_rts_n (uart2_rts_n) | Peripheral UART RTS |
| spiffy1_CLK | SPIFFY 1 Clock |
| spiffy1_CS | SPIFFY 1 Chip Select |
| spiffy1_MOSI | SPIFFY 1 MOSI |

Table 7 GPIO supermux output functions *(continued)*

| Output | Description |
|---------------|---------------------------------|
| spiffy1_MISO | SPIFFY 1 MISO |
| spiffy1_IO2 | SPIFFY I/O 2 |
| spiffy1_IO3 | SPIFFY I/O 3 |
| spiffy1_INT | SPIFFY Interrupt |
| spiffy1_DCX | MIPI-DBI Data/Command Indicator |
| spiffy2_CLK | SPIFFY 2 Clock |
| spiffy2_CS | SPIFFY 2 Chip Select |
| spiffy2_MOSI | SPIFFY 2 MOSI |
| spiffy2_MISO | SPIFFY 2 MISO |
| spiffy2_IO2 | SPIFFY 2 I/O 2 |
| spiffy2_IO3 | SPIFFY 2 I/O 3 |
| spiffy2_INT | SPIFFY 2 Interrupt |
| spiffy2_DCX | MIPI-DBI Data/Command Indicator |
| pcm_in_o | PCM IN |
| pcm_out_o | PCM Out |
| pcm_bclk_o | PCM Bit Clock |
| pcm_sync_o | PCM Sync Output |
| i2s_ssd | I2S Slave Serial Data |
| i2s_sws | I2S Slave Word Select |
| i2s_sck | I2S Slave Clock |
| i2s_msdc | I2S Master Serial Data |
| i2s_mws | I2S Master Word Select |
| i2s_mck | I2S Master Clock |

9 Pin/ball maps

9.1 40-pin QFN pin map

CYW20719 40-pin QFN package is shown in [Figure 6](#).

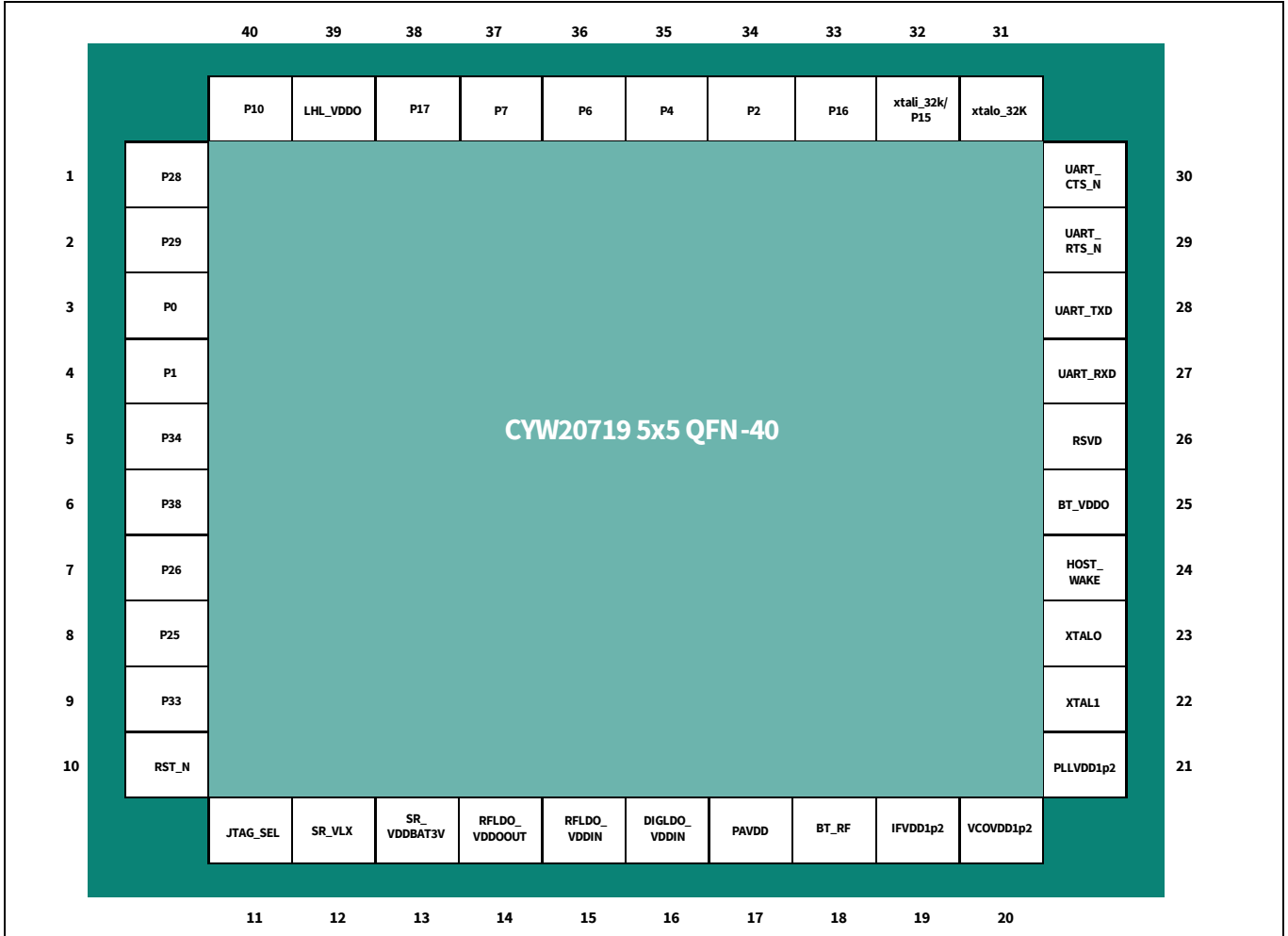


Figure 6 40-pin QFN pin map

9.2 WLCSP ball map

CYW20719 WLCSP package is shown in **Figure 7**.

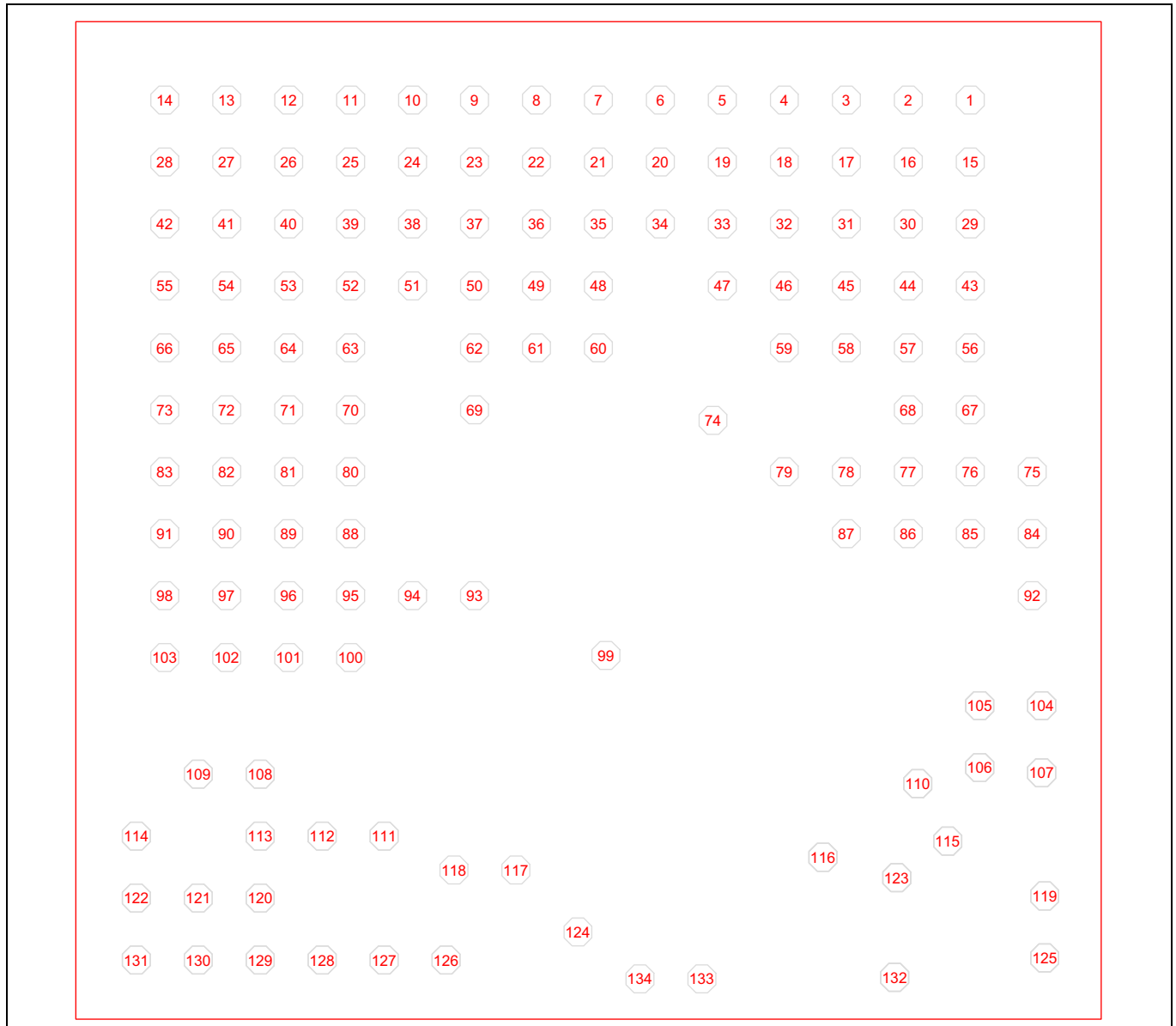


Figure 7 WLCSP ball map

Notes

9. **Figure 7** shows the bottom view of the WLCSP package (Bumps facing up).
10. See **Table 4** and **Table 8** and for additional WLCSP information.
11. **Table 8** shows the package view from the bottom (bumps facing up).
12. Coordinate origin (0, 0) is at the center of the WLCSP package with the bumps facing up.

Pin/ball maps

Table 8 **CYW20719 WLCSP bump coordinates**

| Bump# | NET_NAME | X-COORD (μm) | Y-COORD (μm) |
|--------------|---------------------------|---------------------|---------------------|
| 1 | BT_VDDO | 1232.28 | 1356.88 |
| 2 | BT_VDDC | 1032.28 | 1356.88 |
| 3 | Reserved - Do not connect | 832.28 | 1356.88 |
| 4 | Micn | 632.28 | 1356.88 |
| 5 | ADC_avddBAT | 432.28 | 1356.88 |
| 6 | xtali_32K | 232.29 | 1356.88 |
| 7 | P15 | 32.29 | 1356.88 |
| 8 | VDDO_0 | -167.7 | 1356.88 |
| 9 | VDDO_0 | -367.7 | 1356.88 |
| 10 | VSSO_0 | -567.7 | 1356.88 |
| 11 | VDDO_0 | -767.7 | 1356.88 |
| 12 | P20 | -967.69 | 1356.88 |
| 13 | VSSO_0 | -1167.69 | 1356.88 |
| 14 | VDDO_0 | -1367.69 | 1356.88 |
| 15 | BT_UART_CTS_N | 1232.28 | 1156.88 |
| 16 | Reserved, Connect to GND | 1032.28 | 1156.88 |
| 17 | ADC_AVSSC | 832.28 | 1156.88 |
| 18 | Micp | 632.28 | 1156.88 |
| 19 | Mic_avdd | 432.28 | 1156.88 |
| 20 | xtalo_32K | 232.29 | 1156.88 |
| 21 | Reserved | 32.29 | 1156.88 |
| 22 | P3 | -167.7 | 1156.88 |
| 23 | P4 | -367.7 | 1156.88 |
| 24 | P14 | -567.7 | 1156.88 |
| 25 | VSSO_0 | -767.7 | 1156.88 |
| 26 | VDDO_0 | -967.69 | 1156.88 |
| 27 | P22 | -1167.69 | 1156.88 |
| 28 | VSSO_0 | -1367.69 | 1156.88 |
| 29 | BT_VDDO | 1232.28 | 956.88 |
| 30 | BT_VSSC | 1032.28 | 956.88 |
| 31 | BT_UART_RTS_N | 832.28 | 956.88 |
| 32 | Micbias | 632.28 | 956.88 |
| 33 | ADC_REFGND | 432.28 | 956.88 |
| 34 | ADC_AVSS | 232.29 | 956.88 |
| 35 | xtal_avss | 32.29 | 956.88 |
| 36 | Reserved | -167.7 | 956.88 |
| 37 | P5 | -367.7 | 956.88 |
| 38 | P17 | -567.7 | 956.88 |
| 39 | P19 | -767.7 | 956.88 |

Pin/ball maps

Table 8 CYW20719 WLCSP bump coordinates (continued)

| Bump# | NET_NAME | X-COORD (μm) | Y-COORD (μm) |
|-------|--------------|--------------|--------------|
| 40 | P12 | -967.69 | 956.88 |
| 41 | P28 | -1167.69 | 956.88 |
| 42 | VDDO_0 | -1367.69 | 956.88 |
| 43 | BT_VDDC | 1232.28 | 756.89 |
| 44 | BT_GPIO_2 | 1032.28 | 756.89 |
| 45 | BT_UART_RXD | 832.28 | 756.89 |
| 46 | BT_UART_TXD | 632.28 | 756.89 |
| 47 | Mic_avss | 432.28 | 756.89 |
| 48 | P16 | 32.29 | 756.89 |
| 49 | Reserved | -167.7 | 756.89 |
| 50 | P6 | -367.7 | 756.89 |
| 51 | P18 | -567.7 | 756.89 |
| 52 | P9 | -767.7 | 756.89 |
| 53 | P21 | -967.69 | 756.89 |
| 54 | P1 | -1167.69 | 756.89 |
| 55 | P36 | -1367.69 | 756.89 |
| 56 | BT_VDDO | 1232.28 | 556.89 |
| 57 | BT_VSSC | 1032.28 | 556.89 |
| 58 | BT_VDDC | 832.28 | 556.89 |
| 59 | BT_GPIO_3 | 632.28 | 556.89 |
| 60 | P2 | 32.29 | 556.89 |
| 61 | Reserved | -167.7 | 556.89 |
| 62 | P7 | -367.7 | 556.89 |
| 63 | P10 | -767.7 | 556.89 |
| 64 | P23 | -967.69 | 556.89 |
| 65 | P35 | -1167.69 | 556.89 |
| 66 | VDDO_0 | -1367.69 | 556.89 |
| 67 | BT_TM1 | 1232.28 | 356.89 |
| 68 | BT_CLK_REQ | 1032.28 | 356.89 |
| 69 | P8 | -367.7 | 356.89 |
| 70 | P11 | -767.7 | 356.89 |
| 71 | P13 | -967.69 | 356.89 |
| 72 | VSSO_0 | -1167.69 | 356.89 |
| 73 | P31 | -1367.69 | 356.89 |
| 74 | BT_VDDC | 401.88 | 322.94 |
| 75 | BT_VSSC | 1432.27 | 156.89 |
| 76 | BT_HOST_WAKE | 1232.28 | 156.89 |
| 77 | Reserved | 1032.28 | 156.89 |
| 78 | BT_GPIO_5 | 832.28 | 156.89 |
| 79 | BT_GPIO_4 | 632.28 | 156.89 |

Pin/ball maps

Table 8 CYW20719 WLCSP bump coordinates (continued)

| Bump# | NET_NAME | X-COORD (μm) | Y-COORD (μm) |
|-------|--------------------------|--------------|--------------|
| 80 | P29 | -767.7 | 156.89 |
| 81 | P34 | -967.69 | 156.89 |
| 82 | P39 | -1167.69 | 156.89 |
| 83 | P26 | -1367.69 | 156.89 |
| 84 | Reserved | 1432.27 | -43.1 |
| 85 | Reserved | 1232.28 | -43.1 |
| 86 | BT_DEV_WAKE | 1032.28 | -43.1 |
| 87 | BT_VSSC | 832.28 | -43.1 |
| 88 | P37 | -767.7 | -43.1 |
| 89 | P38 | -967.69 | -43.1 |
| 90 | P24 | -1167.69 | -43.1 |
| 91 | VDDO_0 | -1367.69 | -43.1 |
| 92 | Reserved, Connect to GND | 1432.27 | -243.09 |
| 93 | P0 | -367.7 | -243.09 |
| 94 | P27 | -567.7 | -243.09 |
| 95 | P30 | -767.7 | -243.09 |
| 96 | VSSO_0 | -967.69 | -243.09 |
| 97 | P25 | -1167.69 | -243.09 |
| 98 | P32 | -1367.69 | -243.09 |
| 99 | BT_VDDC | 56.23 | -435.87 |
| 100 | P33 | -767.7 | -443.09 |
| 101 | VSSO_0 | -967.69 | -443.09 |
| 102 | JTAG_SEL | -1167.69 | -443.09 |
| 103 | RST_N | -1367.69 | -443.09 |
| 104 | BT_XTALO | 1462.79 | -597.97 |
| 105 | BT_XTALI | 1262.79 | -597.97 |
| 106 | BT_PLLVDD1p2 | 1262.79 | -797.97 |
| 107 | BT_PLLVSS | 1462.79 | -814.63 |
| 108 | Reserved | -1059.5 | -819 |
| 109 | PMU_DISABLE | -1259.5 | -819 |
| 110 | BT_IFVDD1p2 | 1062.79 | -849.66 |
| 111 | RFLDO_VDDIN1P5 | -659.5 | -1018.99 |
| 112 | VSSC | -859.5 | -1018.99 |
| 113 | PMU_AVSS | -1059.5 | -1018.99 |
| 114 | PMU_AVSS | -1459.49 | -1018.99 |
| 115 | BT_IFVSS | 1159.51 | -1035.5 |
| 116 | BT_PAVDD | 756.99 | -1087.29 |
| 117 | BT_VSSC | -234 | -1128.6 |
| 118 | BT_VSSC | -433.99 | -1128.6 |
| 119 | BT_VCOVSS | 1472.59 | -1212.28 |

Pin/ball maps

Table 8 CYW20719 WLCSP bump coordinates (continued)

| Bump# | NET_NAME | X-COORD (μm) | Y-COORD (μm) |
|-------|-----------------|--------------|--------------|
| 120 | VDDBAT3V | -1059.5 | -1218.99 |
| 121 | SR_VLX | -1259.5 | -1218.99 |
| 122 | Reserved | -1459.49 | -1218.99 |
| 123 | BT_PAVSS | 994.94 | -1153.5 |
| 124 | BT_VSSC | -34 | -1328.59 |
| 125 | BT_VCOVDD1p2 | 1472.59 | -1412.28 |
| 126 | DIGLDO_VDDOUT | -459.5 | -1418.99 |
| 127 | DIGLDO_VDDIN1P5 | -659.5 | -1418.99 |
| 128 | RFLDO_VDDOUT | -859.5 | -1418.99 |
| 129 | SR_VDDBAT3V | -1059.5 | -1418.99 |
| 130 | SR_PVSS | -1259.5 | -1418.99 |
| 131 | Reserved | -1459.49 | -1418.99 |
| 132 | BT_RF | 988.31 | -1475 |
| 133 | BT_VSSC | 365.99 | -1479.96 |
| 134 | BT_VSSC | 165.99 | -1479.96 |

10 Specifications

10.1 Electrical characteristics

Caution: The absolute maximum ratings in the following table indicate levels where permanent damage to the device can occur, even if these limits are exceeded for only a brief duration. Functional operation is not guaranteed under these conditions. Operation at absolute maximum conditions for extended periods can adversely affect long-term reliability of the device.

Table 9 Absolute maximum ratings

| Requirement Parameter | Specifications | | | Unit |
|--|----------------|-----|-------|------|
| | Min | Nom | Max | |
| Maximum junction temperature | – | – | 125 | °C |
| VDD IO (BT_VDDO, VDDO_0) | –0.5 | – | 3.795 | V |
| VDD RF (BT_IFVDD1p2, BT_PLLVDD1p2, BT_VCOVDD1p2, BT_PAVDD) | –0.5 | – | 1.38 | V |
| VddbAT3V/SR_VddbAT3V | –0.5 | – | 3.795 | V |
| DIGLDO_VDDIN1P5 | –0.5 | – | 1.65 | V |
| RFLDO_VDDIN1P5 | –0.5 | – | 1.50 | V |
| MIC_AVDD | –0.5 | – | 3.795 | V |

Table 10 ESD/latch up

| Requirement parameter | Specifications | | | Unit |
|-----------------------|----------------|-----|------|------|
| | Min | Nom | Max | |
| ESD tolerance HBM | –2000 | – | 2000 | V |
| ESD tolerance CDM | –500 | – | 500 | V |
| Latch up | – | 200 | – | mA |

Table 11 Environmental ratings

| Characteristics | Value | Unit |
|-----------------------|-------------|------|
| Operating temperature | –30 to +85 | °C |
| Storage temperature | –40 to +150 | °C |

Note

13.Lowest operating temperature for the 32 kHz xtal is -10°C.

Table 12 Recommended operating conditions

| Parameter | Specifications | | | Unit |
|-------------------------|----------------|-----|------|------|
| | Min | Typ | Max | |
| VDDIO (BT_VDDO, VDDO_0) | 1.76 | 3.0 | 3.63 | V |
| VddbAT3V/SR_VddbAT3V | 1.76 | 3.0 | 3.63 | V |
| MIC_AVDD | 1.76 | 3.0 | 3.63 | V |

10.1.1 Core buck regulator

Table 13 Core buck regulator

| Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------------------|---|------|------|------|------|
| Input supply voltage DC, VBAT | DC voltage range inclusive of disturbances | 1.76 | 3.0 | 3.63 | V |
| CBUCK output current | Low Power Operation Mode (LPOM) only | – | – | 65 | mA |
| Output voltage range | Programmable, 30mV/step default = 1.2 V (bits = 0000) | 1.2 | 1.26 | 1.5 | V |
| Output voltage DC accuracy | Includes load and line regulation | –4 | – | +4 | % |
| LPOM efficiency (high load) | – | – | 85 | – | % |
| LPOM efficiency (low load) | – | – | 80 | – | % |
| Input supply voltage ramp-up time | 0 to 3.3 V | 40 | – | – | µs |

- Minimum capacitor value refers to residual capacitor value after taking into account part-to-part tolerance, DC-bias, temperature, and aging.
- Maximum capacitor value refers to the total capacitance seen at a node where the capacitor is connected. This also includes any decoupling capacitors connected at the load side, if any.

10.1.2 Recommended external component for core buck regulator

Table 14 Recommended external component for core buck regulator

| Parameter | Conditions | Min | Typ | Max | Unit |
|---------------------------------|---|-----|-----|-----|------|
| External output inductor L | 2.2 µH ±25%, DCR=114 mΩ ±20%, ACR<1 Ω (for frequency<1 MHz) | – | 2.2 | – | µH |
| External output capacitor, Cout | 4.7 µF ±10%, 6.3 V, 0402, X5R, MLCC capacitor +board total-ESR < 20 mΩ | – | 4.7 | – | µF |
| External input capacitor, Cin | For SR_VDDBAT pin Ceramic, X5R, 0402, ESR<30 mΩ at 4 MHz, +/-20%, 6.3 V, 10 µF | – | 10 | – | µF |

10.1.3 Recommended external components for RFLDO

Table 15 Recommended external components for RFLDO

| Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|-----------------------------------|-----|-----|-----|------|
| External output capacitor, Co | Total ESR (trace/cap): 5 m–240 mΩ | 0.5 | 2.2 | 4.7 | µF |

10.1.4 Digital I/O characteristics

Table 16 Digital I/O characteristics

| Characteristics | Symbol | Min | Typ | Max | Unit |
|--|-----------------|---------------|-----|------|------|
| Input low voltage (VDDO = 3 V) | V _{IL} | – | – | 0.8 | V |
| Input high voltage (VDDO = 3 V) | V _{IH} | 2.4 | – | – | V |
| Input low voltage (VDDO = 1.8 V) | V _{IL} | – | – | 0.4 | V |
| Input high voltage (VDDO = 1.8 V) | V _{IH} | 1.4 | – | – | V |
| Output low voltage | V _{OL} | – | – | 0.45 | V |
| Output high voltage | V _{OH} | VDDO – 0.45 V | – | – | V |
| Input low current | I _{IL} | – | – | 1.0 | μA |
| Input high current | I _{IH} | – | – | 1.0 | μA |
| Input capacitance | C _{IN} | – | – | 0.4 | pF |
| Output low current (VDDO = 3 V, V _{OL} = 0.5 V) | I _{OL} | – | – | 8.0 | mA |
| Output low current (VDDO = 1.8 V, V _{OL} = 0.5 V) | I _{OL} | – | – | 4.0 | mA |
| Output high current (VDDO = 3 V, V _{OH} = 2.55 V) | I _{OH} | – | – | 8.0 | mA |
| Output high current (VDDO = 1.8 V, V _{OH} = 1.35 V) | I _{OH} | – | – | 4.0 | mA |

10.1.5 ADC electrical characteristics

Table 17 Electrical characteristics

| Parameter | Symbol | Conditions/comments | Min | Typ | Max | Unit |
|---------------------|------------------|---------------------|-----|-----|-----|------|
| Current consumption | I _{TOT} | – | – | 2 | 3 | mA |
| Power down current | – | At room temperature | – | 1 | – | μA |

ADC core specification

| | | | | | | |
|-----------------------|------|--|-----|------|-----|-----|
| ADC reference voltage | VREF | From BG with ±3% accuracy | – | 0.85 | – | V |
| ADC sampling clock | – | – | – | 12 | – | MHz |
| Absolute error | – | Includes gain error, offset and distortion. Without factory calibration. | – | – | 5 | % |
| | | Includes gain error, offset and distortion. After factory calibration. | – | – | 2 | % |
| ENOB | – | For audio application | 12 | 13 | – | Bit |
| | | For static measurement | 10 | – | – | |
| ADC input full scale | FS | For audio application | – | 1.6 | – | |
| | | For static measurement | 1.8 | – | 3.6 | |
| Conversion rate | – | For audio application | 8 | 16 | – | kHz |

Note

14. Conditional requirement for the measurement time of 10 μs. Relaxed with longer measurement time for each GPIO input channel.

Specifications

Table 17 Electrical characteristics (continued)

| Parameter | Symbol | Conditions/comments | Min | Typ | Max | Unit |
|------------------|-----------------|------------------------|-----|-----|-----|------|
| Signal bandwidth | - | For audio application | 20 | - | 8K | Hz |
| | | For static measurement | - | DC | - | |
| Input impedance | R _{IN} | For audio application | 10 | - | - | kΩ |
| | | For static measurement | 500 | - | - | |
| Startup time | - | For audio application | - | 10 | - | ms |
| | | For static measurement | - | 20 | - | μs |

MIC PGA specifications

| | | | | | | |
|--------------------------|---|------------------------------|---|---|----|----|
| MIC PGA gain range | - | - | 0 | - | 42 | dB |
| MIC PGA gain step | - | - | - | 1 | - | dB |
| PGA input referred noise | - | At 42 dB PGA gain A-weighted | - | - | 4 | μV |

MIC Bias Specifications

| | | | | | | |
|---------------------------------------|---|--|----|-----|-----|----|
| MIC bias output voltage | - | At 3 V supply, 25°C, default settings | - | 2.4 | - | V |
| MIC bias loading current | - | - | - | - | 3 | mA |
| MIC bias noise | - | Refers to PGA input 20 Hz to 8 kHz, A-weighted | - | - | 3 | μV |
| MIC bias PSRR | - | at 1 kHz | 40 | - | - | dB |
| ADC SNR | - | A-weighted 0 dB PGA gain, Temperature= 25°C | - | 78 | - | dB |
| ADC THD + N | - | -3 dBFS input 0 dB PGA gain, Temperature= 25°C | - | 70 | - | dB |
| GPIO input voltage | | Always lower than avddBAT | - | - | 3.6 | V |
| GPIO source impedance ^[14] | - | Resistance | - | - | 1 | kΩ |
| | | Capacitance | - | - | 10 | pF |

Note

14. Conditional requirement for the measurement time of 10 μs. Relaxed with longer measurement time for each GPIO input channel.

10.1.6 Current consumption

In **Table 18**, current consumption measurements are taken at input of VBAT and VDDIO combined (LDOIN = VDDIO = 3.0 V).

Table 18 Current consumption Bluetooth®/LE

| Operational mode | Conditions | Typ | Unit |
|------------------------------|--|-----|------|
| HCI | 48 MHz with Pause | 1.1 | mA |
| | 48 MHz Without Pause | 2.2 | mA |
| RX | Continuous RX | 5.9 | mA |
| TX | Continuous TX - 0 dBm | 5.6 | mA |
| PDS | | 61 | µA |
| HID-Off | 32 kHz XTAL and 16 KB Retention RAM on | 1.6 | µA |
| Advertising | Unconnectable - 1 s | 14 | µA |
| | Connectable undirected - 1 s | 17 | µA |
| LE connection - SDS | Master - 1 s | 16 | µA |
| | Slave - 1 s | 17 | µA |
| Page scan - PDS | Interlaced - R1 | 122 | µA |
| Sniff - PDS | 500 ms Sniff, 1 attempt, 0 timeout - Master | 132 | µA |
| | 500 ms Sniff, 1 attempt, 0 timeout - Slave | 138 | µA |
| Bi-directional data exchange | Continuous DM5 or DH5 packets - Master/Slave | 6.9 | mA |

10.2 RF specifications

Note Table 19 and **Table 20** apply to single-ended industrial temperatures. Unused inputs are left open.

Table 19 Receiver RF specifications

| Parameter | Mode and conditions | Min. | Typ. | Max. | Unit |
|--|------------------------------|------|-----------------------|------|------|
| Frequency range | – | 2402 | – | 2480 | MHz |
| RX sensitivity (QFN) ^[15] | GFSK, 0.1% BER, 1 Mbps | – | –92.0 ^[15] | – | dBm |
| | π/4-DQPSK, 0.01% BER, 2 Mbps | – | –94.0 ^[16] | – | dBm |
| | 8-DPSK, 0.01% BER, 3 Mbps | – | –88.0 ^[16] | – | dBm |
| RX sensitivity (WLCSP) ^[15] | GFSK, 0.1% BER, 1 Mbps | – | –91.5 ^[16] | – | dBm |
| | π/4-DQPSK, 0.01% BER, 2 Mbps | – | –93.5 ^[16] | – | dBm |
| | 8-DPSK, 0.01% BER, 3 Mbps | – | –87.5 ^[16] | – | dBm |

Notes

- 15. Dirty TX is off.
- 16. Up to 1dB of variation may potentially be seen from typical sensitivity specs due to the chip, board and associated variations.
- 17. The receiver sensitivity is measured at BER of 0.1% on the device interface.
- 18. Desired signal is 10 dB above the reference sensitivity level (defined as –70 dBm).
- 19. Desired signal is 3 dB above the reference sensitivity level (defined as –70 dBm).
- 20. Desired signal is –64 dBm Bluetooth®-modulated signal, interferer 1 is –39 dBm sine wave at frequency f1, interferer 2 is –39 dBm Bluetooth® modulated signal at frequency f2, $f_0 = 2*f_1 - f_2$, and $|f_2 - f_1| = n*1$ MHz, where n is 3, 4, or 5. For the typical case, n = 4.

Specifications

Table 19 Receiver RF specifications (continued)

| Parameter | Mode and conditions | Min. | Typ. | Max. | Unit |
|---|-------------------------------------|------|-------|-------|------|
| Maximum input | All data rates | - | - | -20 | dBm |
| GFSK modulation | | | | | |
| C/I cochannel | GFSK, 0.1% BER ^[15] | - | - | 11.0 | dB |
| C/I 1 MHz adjacent channel | GFSK, 0.1% BER ^[16] | - | - | 0 | dB |
| C/I 2 MHz adjacent channel | GFSK, 0.1% BER ^[17] | - | - | -30.0 | dB |
| C/I ≥ 3 MHz adjacent channel | GFSK, 0.1% BER ^[15] | - | - | -40.0 | dB |
| C/I image channel | GFSK, 0.1% BER ^[17] | - | - | -9.0 | dB |
| C/I 1 MHz adjacent to image channel | GFSK, 0.1% BER ^[17] | - | - | -20.0 | dB |
| QPSK modulation | | | | | |
| C/I cochannel | p/4-DQPSK, 0.1% BER ^[17] | - | - | 13.0 | dB |
| C/I 1 MHz adjacent channel | p/4-DQPSK, 0.1% BER ^[18] | - | - | 0 | dB |
| C/I 2 MHz adjacent channel | p/4-DQPSK, 0.1% BER ^[17] | - | - | -30.0 | dB |
| C/I ≥ 3 MHz adjacent channel | p/4-DQPSK, 0.1% BER ^[19] | - | - | -40.0 | dB |
| C/I image channel | p/4-DQPSK, 0.1% BER ^[17] | - | - | -9.0 | dB |
| C/I 1 MHz adjacent to image channel | p/4-DQPSK, 0.1% BER ^[17] | - | - | -20.0 | dB |
| 8PSK modulation | | | | | |
| C/I cochannel | 8-DPSK, 0.1% BER ^[17] | - | - | 21.0 | dB |
| C/I 1 MHz adjacent channel | 8-DPSK, 0.1% BER ^[17] | - | - | 5.0 | dB |
| C/I 2 MHz adjacent channel | 8-DPSK, 0.1% BER ^[17] | - | - | -25.0 | dB |
| C/I ≥ 3 MHz adjacent channel | 8-DPSK, 0.1% BER ^[19] | - | - | -33.0 | dB |
| C/I image channel | 8-DPSK, 0.1% BER ^[17] | - | - | 0 | dB |
| C/I 1 MHz adjacent to image channel | 8-DPSK, 0.1% BER ^[17] | - | - | 13 | dB |
| Out-of-band blocking performance (CW)^[18] | | | | | |
| 30 MHz to 2000 MHz | BDR GFSK 0.1% BER | - | -10.0 | - | dBm |
| 2000 MHz to 2399 MHz | BDR GFSK 0.1% BER | - | -27.0 | - | dBm |
| 2498 MHz to 3000 MHz | BDR GFSK 0.1% BER | - | -27.0 | - | dBm |
| 3000 MHz to 12.75 GHz | BDR GFSK 0.1% BER | - | -10.0 | - | dBm |
| Inter-modulation performance^[15] | | | | | |
| Bluetooth®, interferer signal level | BDR GFSK 0.1% BER | - | - | -39.0 | dBm |

Notes

15. Dirty TX is off.
16. Up to 1dB of variation may potentially be seen from typical sensitivity specs due to the chip, board and associated variations.
17. The receiver sensitivity is measured at BER of 0.1% on the device interface.
18. Desired signal is 10 dB above the reference sensitivity level (defined as -70 dBm).
19. Desired signal is 3 dB above the reference sensitivity level (defined as -70 dBm).
20. Desired signal is -64 dBm Bluetooth®-modulated signal, interferer 1 is -39 dBm sine wave at frequency f1, interferer 2 is -39 dBm Bluetooth® modulated signal at frequency f2, $f_0 = 2 * f_1 - f_2$, and $|f_2 - f_1| = n * 1 \text{ MHz}$, where n is 3, 4, or 5. For the typical case, $n = 4$.

Specifications

Table 19 Receiver RF specifications (continued)

| Parameter | Mode and conditions | Min. | Typ. | Max. | Unit |
|---------------------------|---------------------|------|------|-------|------|
| Spurious emissions | | | | | |
| 30 MHz to 1 GHz | – | – | – | –57.0 | dBm |
| 1 GHz to 12.75 GHz | – | – | – | –55.0 | dBm |

Notes

- 15. Dirty TX is off.
- 16. Up to 1dB of variation may potentially be seen from typical sensitivity specs due to the chip, board and associated variations.
- 17. The receiver sensitivity is measured at BER of 0.1% on the device interface.
- 18. Desired signal is 10 dB above the reference sensitivity level (defined as –70 dBm).
- 19. Desired signal is 3 dB above the reference sensitivity level (defined as –70 dBm).
- 20. Desired signal is –64 dBm Bluetooth®-modulated signal, interferer 1 is –39 dBm sine wave at frequency f1, interferer 2 is –39 dBm Bluetooth® modulated signal at frequency f2, $f_0 = 2 \cdot f_1 - f_2$, and $|f_2 - f_1| = n \cdot 1$ MHz, where n is 3, 4, or 5. For the typical case, n = 4.

Table 20 Transmitter RF specifications

| Parameter | Min | Typ | Max | Unit |
|--|------|-----|-------|----------------|
| Transmitter section | | | | |
| Frequency range | 2402 | – | 2480 | MHz |
| GFSK TX power | – | 5 | – | dBm |
| EDR TX power | – | 0 | – | dBm |
| 20 dB bandwidth | – | 930 | 1000 | kHz |
| Adjacent channel power | | | | |
| $ M - N = 2$ | – | – | –20 | dBm |
| $ M - N \geq 3$ | – | – | –40 | dBm |
| Out-of-band spurious emission | | | | |
| 30 MHz to 1 GHz | – | – | –36.0 | dBm |
| 1 GHz to 12.75 GHz | – | – | –30.0 | dBm |
| 1.8 GHz to 1.9 GHz | – | – | –47.0 | dBm |
| 5.15 GHz to 5.3 GHz | – | – | –47.0 | dBm |
| LO performance | | | | |
| Initial carrier frequency tolerance | –75 | – | +75 | kHz |
| Frequency drift | | | | |
| DH1 packet | –25 | – | +25 | kHz |
| DH3 packet | –40 | – | +40 | kHz |
| DH5 packet | –40 | – | +40 | kHz |
| Drift rate | –20 | | 20 | kHz/50 μ s |
| Frequency deviation | | | | |
| Average deviation in payload (sequence used is 00001111) | 140 | – | 175 | kHz |
| Maximum deviation in payload (sequence used is 10101010) | 115 | – | – | kHz |
| Channel spacing | – | 1 | – | MHz |
| Modulation accuracy | | | | |
| p/4-DQPSK frequency stability | –10 | – | 10 | kHz |

Specifications

Table 20 Transmitter RF specifications (continued)

| Parameter | Min | Typ | Max | Unit |
|-----------------------------------|-----|-----|-----|------|
| p/4-DQPSK RMS DEVM | – | – | 20 | % |
| p/4-QPSK Peak DEVM | – | – | 35 | % |
| p/4-DQPSK 99% DEVM | – | – | 30 | % |
| 8-DPSK frequency stability | –10 | – | 10 | kHz |
| 8-DPSK RMS DEVM | – | – | 13 | % |
| 8-DPSK Peak DEVM | – | – | 25 | % |
| 8-DPSK 99% DEVM | – | – | 20 | % |
| In-band spurious emissions | | | | |
| 1.0 MHz < M – N < 1.5 MHz | – | – | –26 | dBc |
| 1.5 MHz < M – N < 2.5 MHz | – | – | –20 | dBm |
| M – N > 2.5 MHz | – | – | –40 | dBm |

Table 21 Bluetooth® LE RF specifications

| Parameter | Conditions | Min | Typ | Max | Unit |
|--|---------------------------|------|-----------------------|------|------|
| Frequency range | N/A | 2402 | – | 2480 | MHz |
| RX sensitivity (QFN) ^[21] | LE GFSK, 0.1% BER, 1 Mbps | – | –95.5 ^[22] | – | dBm |
| RX sensitivity (WLCSP) ^[21] | LE GFSK, 0.1% BER, 1 Mbps | – | –94.5 ^[22] | – | dBm |
| TX power | N/A | – | 5.5 | – | dBm |
| Mod Char: Delta F1 average | N/A | 225 | 255 | 275 | kHz |
| Mod Char: Delta F2 max ^[22] | N/A | 99.9 | – | – | % |
| Mod Char: Ratio | N/A | 0.8 | 0.95 | – | % |

Notes

21.Dirty Tx is Off.

22.Up to 1 dB of variation may potentially be seen from typical sensitivity specs due to the chip, board and associated variations.

23.At least 99.9% of all delta F2 max frequency values recorded over 10 packets must be greater than 185 kHz.

Specifications

Table 22 BLE2M RF specifications

| Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--------------------------------|-------------|------|-------|------|----------|
| Frequency range | N/A | 2402 | – | 2480 | MHz |
| RX sensitivity ^[24] | 255 Packets | – | –90.5 | – | dBm |
| TX power | N/A | – | 5.5 | – | dBm |
| Mod char: Delta F1 average | N/A | 450 | 500 | 550 | kHz |
| Mod char: Delta F2 max | N/A | 370 | – | – | kHz |
| Mod char: Ratio | N/A | 0.8 | – | – | % |
| Frequency drift | N/A | –50 | – | 50 | kHz |
| Drift rate | N/A | –20 | – | 20 | kHz/50μs |

Note

24.Dirty Tx is Off.

Table 23 CYW20719 GPS and GLONASS band spurious emission

| Parameter | Conditions | Min | Typ | Max | Unit |
|---------------|------------|-----|------|-----|--------|
| 1570-1580 MHz | GPS | – | –160 | – | dBm/Hz |
| 1592-1610 MHz | GLONASS | – | –159 | – | dBm/Hz |

10.3 Timing and AC characteristics

In this section, use the numbers listed in the Reference column of each table to interpret the following timing diagrams.

10.3.1 UART timing

Table 24 UART timing specifications

| Reference | Characteristics | Min | Typ | Max | Unit |
|-----------|---|-----|-----|------|-------------|
| 1 | Delay time, UART_CTS_N low to UART_TXD valid | – | – | 1.50 | Bit periods |
| 2 | Setup time, UART_CTS_N high before midpoint of stop bit | – | – | 0.67 | Bit periods |
| 3 | Delay time, midpoint of stop bit to UART_RTS_N HIGH | – | – | 1.33 | Bit periods |

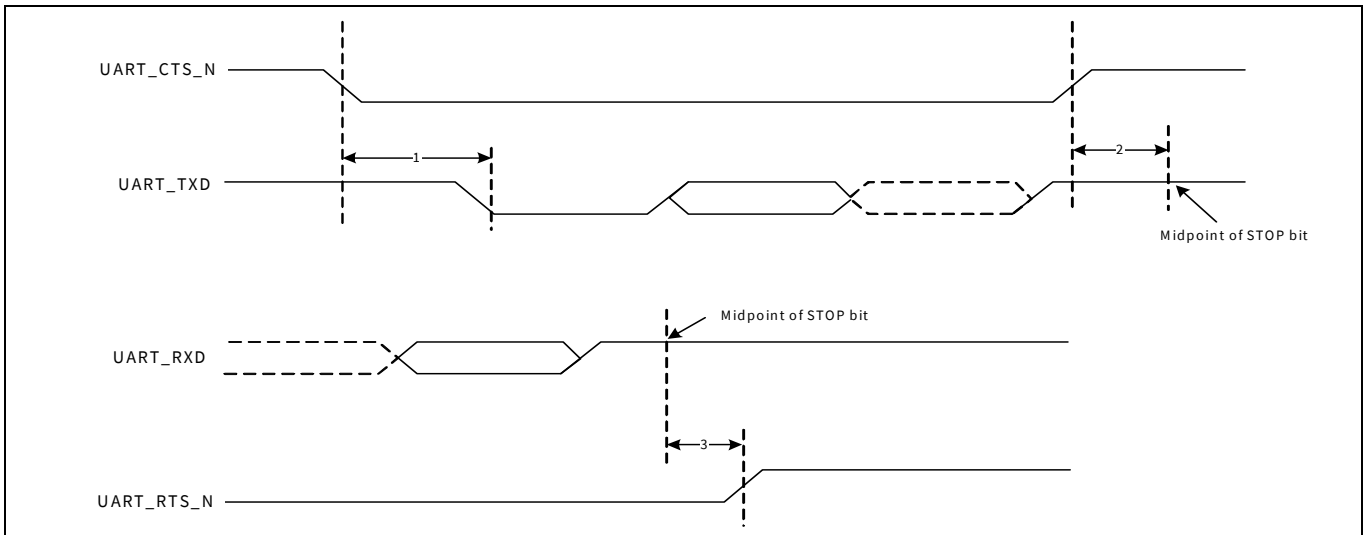


Figure 8 UART timing

10.3.2 SPI timing

The SPI interface can be clocked from 1 to 12 MHz and 24 MHz.

Table 25 and **Figure 9** show the timing requirements when operating in SPI Mode 0 and 2.

Table 25 SPI Mode 0 and 2

| Reference | Characteristics | Min | Max | Unit |
|-----------|--|-------|-------|------|
| 1 | Time from master assert SPI_CSN to first clock edge | 45 | – | ns |
| 2 | Hold time for MOSI data lines | 12 | ½ SCK | ns |
| 3 | Time from last sample on MOSI/MISO to slave deassert SPI_INT | 0 | 100 | ns |
| 4 | Time from slave deassert SPI_INT to master deassert SPI_CSN | 0 | – | ns |
| 5 | Idle time between subsequent SPI transactions | 1 SCK | – | ns |

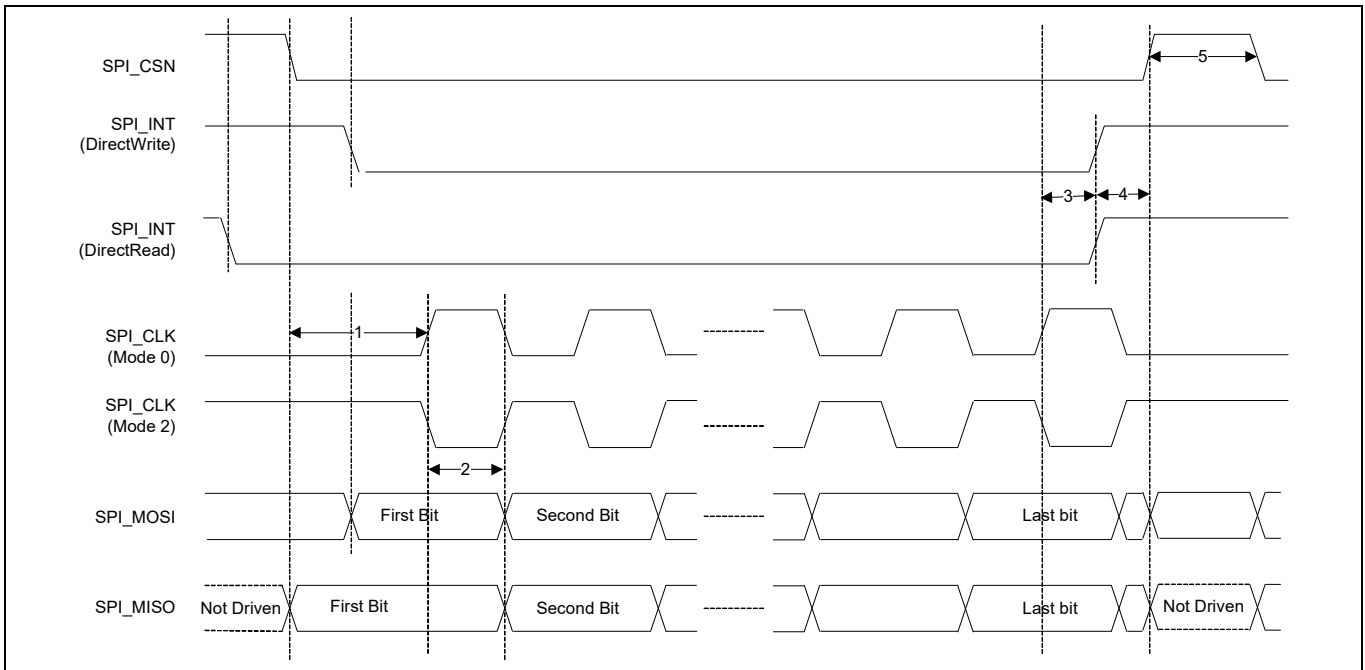


Figure 9 SPI timing, Mode 0 and 2

Table 26 and **Figure 10** show the timing requirements when operating in SPI Mode 0 and 2.

Table 26 SPI Mode 1 and 3

| Reference | Characteristics | Min | Max | Unit |
|-----------|--|-------|-------|------|
| 1 | Time from master assert SPI_CSN to first clock edge | 45 | – | ns |
| 2 | Hold time for MOSI data lines | 12 | ½ SCK | ns |
| 3 | Time from last sample on MOSI/MISO to slave deassert SPI_INT | 0 | 100 | ns |
| 4 | Time from slave deassert SPI_INT to master deassert SPI_CSN | 0 | – | ns |
| 5 | Idle time between subsequent SPI transactions | 1 SCK | – | ns |

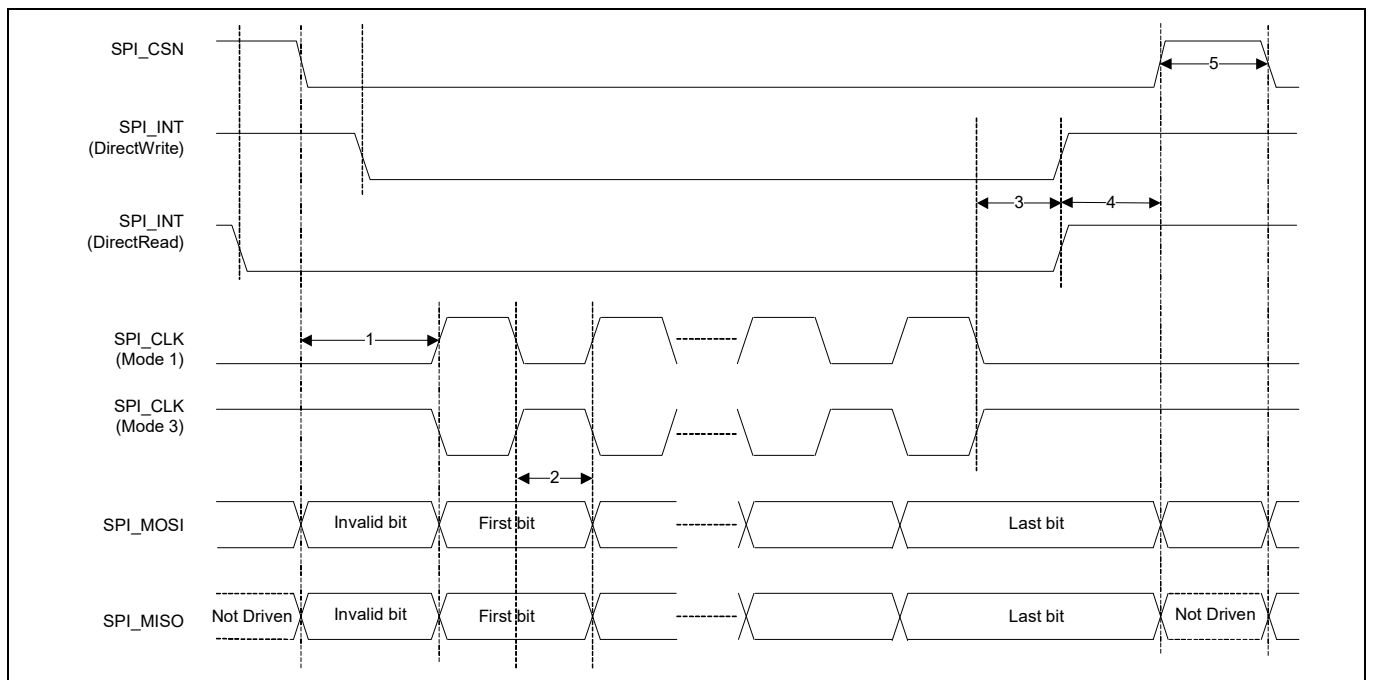


Figure 10 SPI timing, Mode 1 and 3

10.3.3 I²C compatible interface timing

The specifications in [Table 27](#) references [Figure 11](#).

Table 27 I²C Compatible Interface Timing Specifications (up to 1 MHz)

| Reference | Characteristics | Min. | Max. | Unit |
|-----------|--------------------------------------|------|------|------|
| 1 | Clock frequency | - | 100 | kHz |
| | | | 400 | |
| | | | 800 | |
| | | | 1000 | |
| 2 | START condition setup time | 650 | - | ns |
| 3 | START condition hold time | 280 | - | |
| 4 | Clock low time | 650 | - | |
| 5 | Clock high time | 280 | - | |
| 6 | Data input hold time ^[25] | 0 | - | |
| 7 | Data input setup time | 100 | - | |
| 8 | STOP condition setup time | 280 | - | |
| 9 | Output valid from clock | - | 400 | |
| 10 | Bus free time ^[26] | 650 | - | |

Notes

25.As a transmitter, 125 ns of delay is provided to bridge the undefined region of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

26.Time that the CBUS must be free before a new transaction can start.

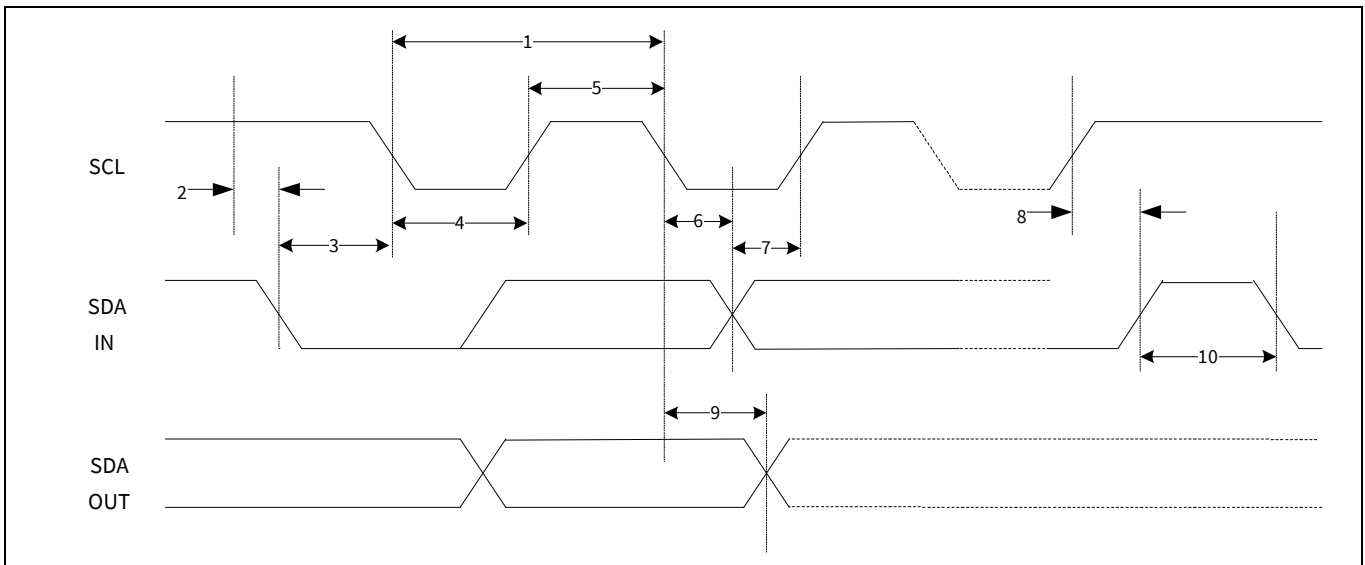


Figure 11 I²C interface timing diagram

Table 28 Timing for I²S transmitters and receivers

| | Transmitter | | | | Receiver | | | | Notes |
|--|--------------|--------------|--------------|--------|--------------|--------------|-------------|-----|-------|
| | Lower limit | | Upper limit | | Lower limit | | Upper limit | | |
| | Min | Max. | Min | Max | Min | Max | Min | Max | |
| Clock Period T | T_{tr} | - | - | - | T_r | - | - | - | [27] |
| Master mode: Clock generated by transmitter or receiver | | | | | | | | | |
| HIGH t_{HC} | $0.35T_{tr}$ | - | - | - | $0.35T_{tr}$ | - | - | - | [28] |
| LOW t_{LC} | $0.35T_{tr}$ | - | - | - | $0.35T_{tr}$ | - | - | - | [28] |
| Slave mode: Clock accepted by transmitter or receiver | | | | | | | | | |
| HIGH t_{HC} | - | $0.35T_{tr}$ | - | - | - | $0.35T_{tr}$ | - | - | [29] |
| LOW t_{LC} | - | $0.35T_{tr}$ | - | - | - | $0.35T_{tr}$ | - | - | [29] |
| Rise time t_{RC} | - | - | $0.15T_{tr}$ | - | - | - | - | - | [30] |
| Transmitter | | | | | | | | | |
| Delay t_{dtr} | - | - | - | $0.8T$ | - | - | - | - | [31] |
| Hold time t_{htr} | 0 | - | - | - | - | - | - | - | [30] |
| Receiver | | | | | | | | | |
| Setup time t_{sr} | - | - | - | - | $0.2T_{tr}$ | - | - | - | [32] |
| Hold time t_{hr} | - | - | - | - | $0.2T_{tr}$ | - | - | - | [32] |

Notes

27. The system clock period T must be greater than T_{tr} and T_r because both the transmitter and receiver have to be able to handle the data transfer rate.
28. At all data rates in master mode, the transmitter or receiver generates a clock signal with a fixed mark/space ratio. For this reason, t_{HC} and t_{LC} are specified with respect to T.
29. In slave mode, the transmitter and receiver need a clock signal with minimum HIGH and LOW periods so that they can detect the signal. So long as the minimum periods are greater than $0.35T_r$, any clock that meets the requirements can be used.
30. Because the delay (t_{dtr}) and the maximum transmitter speed (defined by T_{tr}) are related, a fast transmitter driven by a slow clock edge can result in t_{dtr} not exceeding t_{RC} which means t_{htr} becomes zero or negative. Therefore, the transmitter has to guarantee that $t_{htr} \geq$ zero, so long as the clock rise-time t_{RC} is not more than t_{RCmax} , where t_{RCmax} is not less than $0.15T_{tr}$.
31. To allow data to be clocked out on a falling edge, the delay is specified with respect to the rising edge of the clock signal and T, always giving the receiver sufficient setup time.
32. The data setup and hold time must not be less than the specified receiver setup and hold time.

Specifications

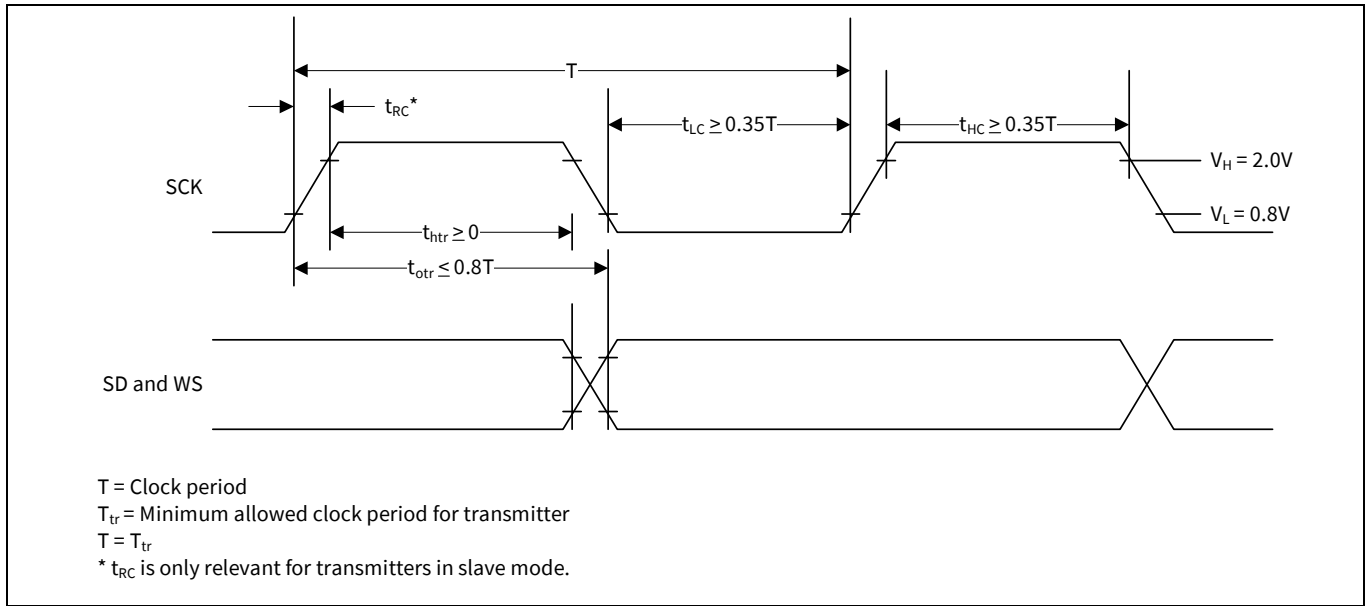


Figure 12 I²S transmitter timing

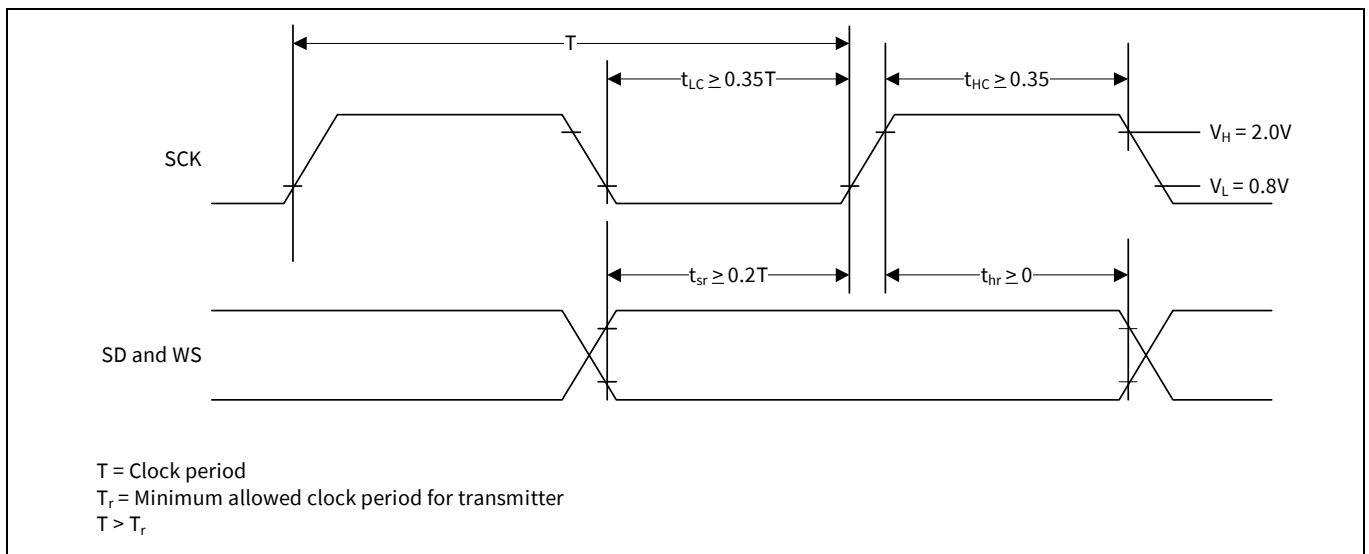


Figure 13 I²S receiver timing

11 Mechanical information

11.1 40-pin QFN package

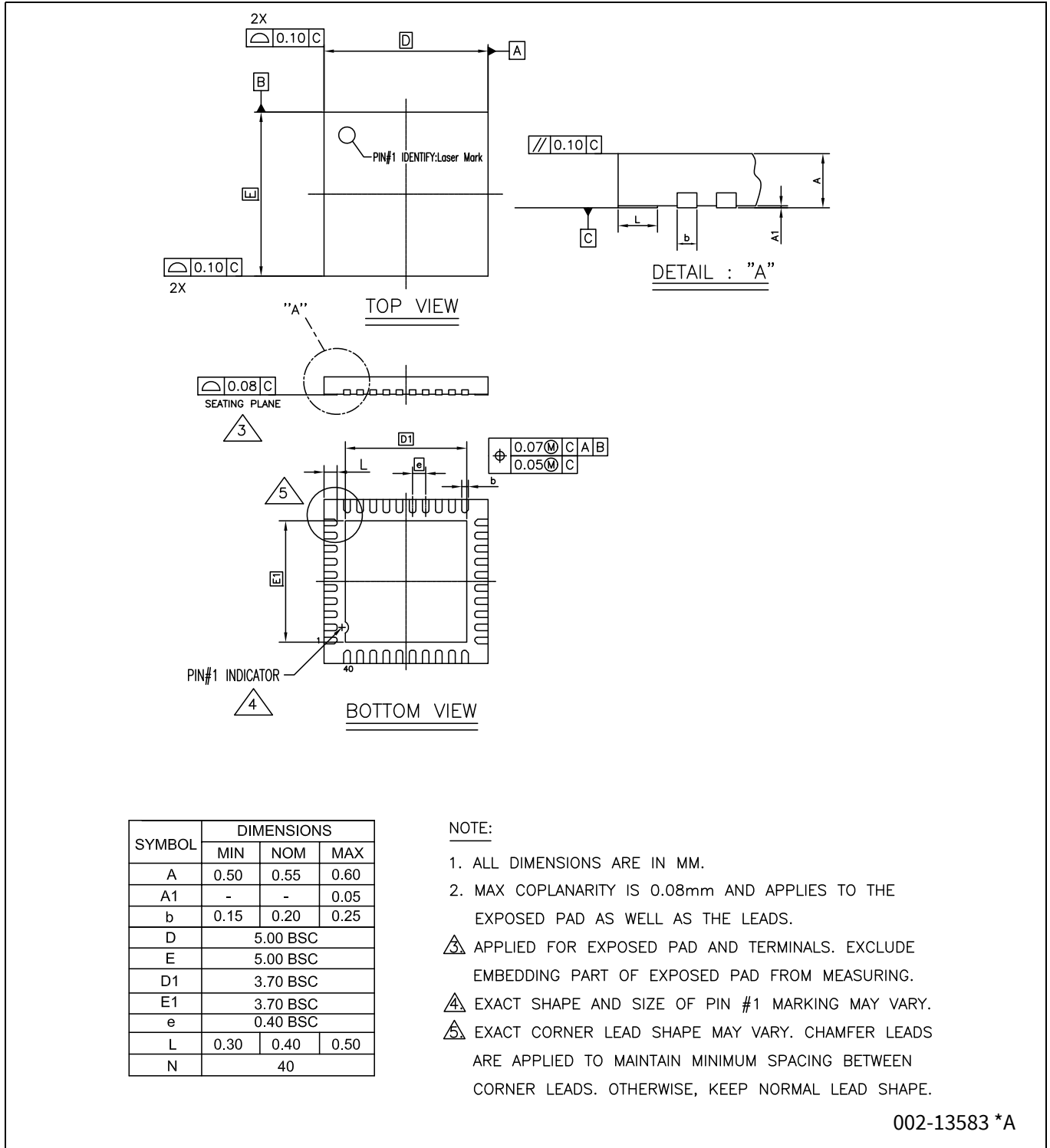


Figure 14 CYW20719 5.0 mm × 5.0 mm 40-pin QFN package (PG-VQFN-40)

11.2 WLCSP package

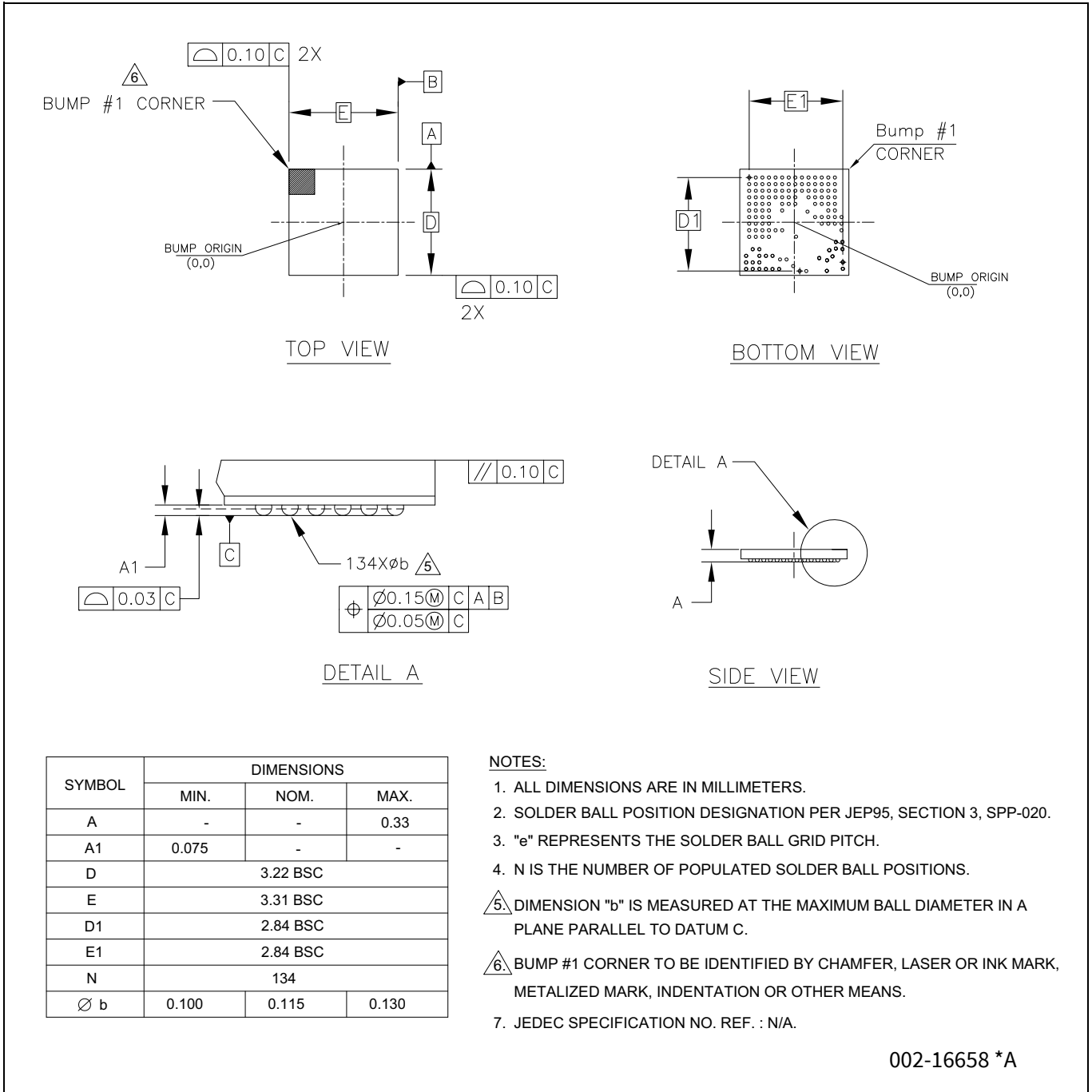


Figure 15 CYW20719 3.3 × 3.2 × 0.33 mm 134-balls WLCSP package (SG-XFWLB-134)

11.3 WLCSP package keep-out

Figure 16 shows the top view of the WLCSP package (Bumps facing down).

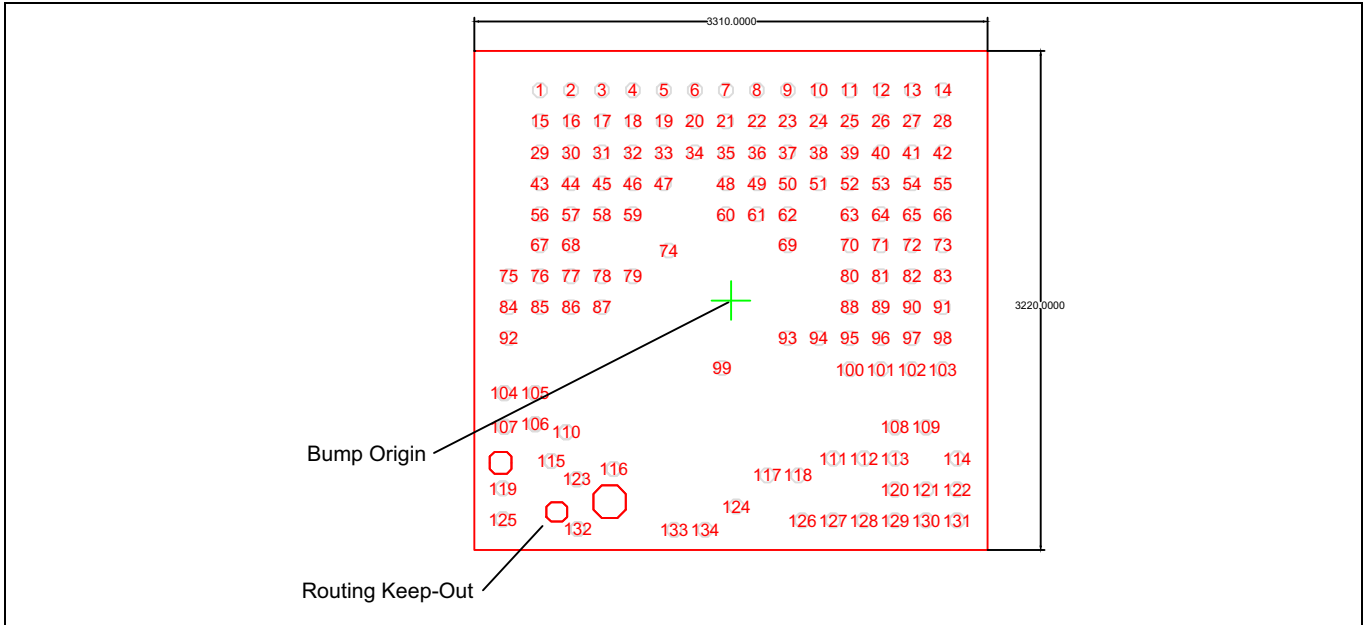


Figure 16 CYW20719YB2 WLCSP keep-out model

11.4 Tape reel and packaging specifications

Table 29 CYW20719 tape reel specifications

| Parameter | Value |
|-------------------|-----------|
| Quantity per reel | 5000 |
| Reel diameter | 13 inches |
| Hub diameter | 4 inches |
| Tape width | 12 mm |
| Tape pitch | 8 mm |

The top-left corner of CYW20719 package is situated near the sprocket holes, as shown in Figure 17.

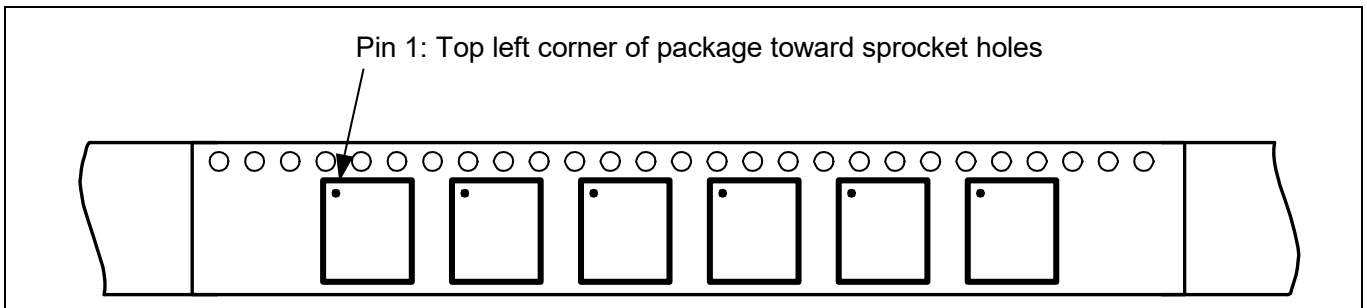


Figure 17 Pin 1 orientation

Ordering information

12 Ordering information

Table 30 Ordering information

| Product | Package | Ambient operating temperature |
|-----------------|--------------------------|-------------------------------|
| CYW20719B2KWB9G | 3.2 × 3.1 134-Ball WLCSP | -30°C to 85°C |
| CYW20719B2KUMLG | 5 × 5 40-pin QFN | -30°C to 85°C |

13 Acronyms

Table 31 Acronyms used in this document

| Term | Description |
|-------------|--|
| AFH | adaptive frequency hopping |
| ATT | Attribute Protocol |
| BBC | Bluetooth® Baseband Core |
| BDR | basic data rate |
| BR | basic data rate |
| BQS | Bluetooth® Qualification Body |
| CRC | cyclic redundancy check |
| ED | erroneous data |
| EIR | extended inquiry response |
| EPR | encryption pause resume |
| FEC | forward error correction |
| FPU | floating point unit |
| GATT | Generic Attribute Profile |
| GAP | generic access profile |
| GFSK | Gaussian Frequency Shift Keying |
| GPIO | general-purpose I/O |
| HCI | host control interface |
| IF | intermediate frequency |
| JTAG | Joint Test Action Group |
| L2CAP | Logical Link Control and Adaptation Protocol |
| LCU | link control unit |
| LDO | low drop-out |
| LE | low energy |
| LM | Link Manager |
| LO | local oscillator |
| LPO | low power oscillator |
| LSTO | link supervision time out |
| PA | power amplifier |
| PBF | packet boundary flag |
| PDM | pulse density modulation |
| PDS | Power down sleep |
| PLL | phase locked loop |
| PMU | power management unit |
| POR | power-on reset |
| PRBS | Pseudo Random Binary Sequence |
| PWM | pulse width modulation |
| QFN | quad flat no-lead |
| QoS | quality of service |

Acronyms

Table 31 Acronyms used in this document *(continued)*

| Term | Description |
|---------------|--|
| RAM | random access memory |
| RC oscillator | A resistor-capacitor oscillator is a circuit composed of an amplifier, which provides the output signal, and a resistor-capacitor network, which controls the frequency of the signal. |
| RF | radio frequency |
| ROM | read-only memory |
| RX/TX | receive/transmit |
| SCO | synchronous connection-oriented |
| SDP | Service Discovery Protocol |
| SDS | Shut Down Sleep |
| SPI | serial peripheral interface |
| SPIFFY | serial peripheral interface fully functional |
| SSP | secure simple pairing |
| SSR | sniff subrating |
| SWD | serial wire debug |
| TSSI | transmit signal strength indicator |
| UART | universal asynchronous receiver/transmitter |
| WLCSP | wafer level chip scale package |

14 Document conventions

14.1 Units of measure

Table 32 Units of measure

| Symbol | Unit of measure |
|--------|--------------------------------|
| °C | degrees Celsius |
| dB | decibel |
| dBi | decibels relative to isotropic |
| dBm | decibel-milliwatts |
| GHz | gigahertz |
| Hz | hertz |
| KB | 1024 bytes |
| kHz | kilohertz |
| kΩ | kilo ohm |
| kV | kilovolt |
| mA | milliamperes |
| Mbps | megabits per second |
| MHz | megahertz |
| MΩ | mega-ohm |
| mm | millimeters |
| Msp/s | megasamples per second |
| mV | millivolt |
| μA | microampere |
| μF | microfarad |
| μm | micrometers |
| μs | microsecond |
| μV | microvolt |
| μW | microwatt |
| mA | milliampere |
| mΩ | milliohm |
| ms | millisecond |
| mV | millivolt |
| nA | nanoampere |
| ns | nanosecond |
| W | ohm |
| pF | picofarad |
| ppm | parts per million |
| ps | picosecond |
| s | second |
| sps | samples per second |
| V | volt |

Revision history

Revision history

| Document revision | Date | Description of changes |
|-------------------|------------|--|
| *G | 2022-02-14 | Removed “Preliminary” status. Updated Table 4 . |
| *H | 2023-01-17 | Migrated to the Infineon template. |
| *I | 2024-05-27 | Updated Bluetooth® version to 5.4. |

Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

The Bluetooth® word mark and logos are registered trademarks owned by Bluetooth SIG, Inc., and any use of such marks by Infineon is under license.

Edition 2024-05-27

Published by

Infineon Technologies AG
81726 Munich, Germany

© 2024 Infineon Technologies AG.
All Rights Reserved.

Do you have a question about this document?

Email:

erratum@infineon.com

Document reference

002-26644 Rev. *1

IMPORTANT NOTICE

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.



WARNINGS

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

-  [View CYW20719B2KWB9GT on WIN SOURCE](#)
-  [Infineon Technologies Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management